

Introduction au Microusinage par laser

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01/12/2011

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CONTENU

- Introduction Optec
- Objectif de la présentation
- Généralités sur le laser
- Traitement des matériaux par laser
- Tendances du marché
- Point de vue d'un intégrateur
- Quelques ex de machines

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Micro Usinage par laser Excimer et laser Ultra Rapide pour les domaines du semiconducteur, électronique, optronique, médical et marquage de sécurité :-

- Excimer & lasers Ultra Rapides
- Centre d'usinage laser standard
- Solutions spécifiques
- Sous ensembles opto-mécaniques
- Expertise Process
- SAV



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Quelques exemples de systèmes



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Notre expertise dans le domaine du traitement Athermique par laser :

Nous intégrons des sources lasers avec des durées d'impulsions comprises entre fs-ns, des longueurs d'ondes situées dans le spectre UV-IR, en combinaison avec des techniques de projection ou d'usinage au point focal.

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Notre expertise dans le domaine du traitement Athermique par laser :

From P.R. Herman et al./Applied Surface Science 154-155 (2000) 577-588

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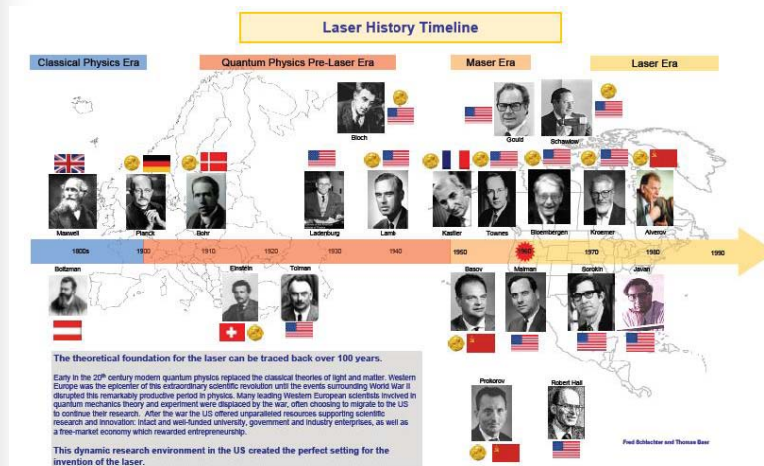
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Objectifs

- Passer en revue les différents paramètres Laser, les techniques et procédés d'usinage ainsi que leur interaction au regard des besoins du marché et des applications actuelles et à venir.

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Un peu d'histoire...

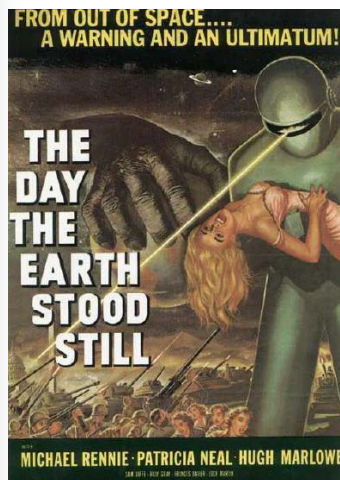


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Le laser ce n'est pas...



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Mais c'est aussi...

Un rayon lumineux

Pointeur laser



Spectacle

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Le laser c'est...

Dans l'industrie

Découpe de plaques, tubes, pièces métalliques ...

Laser à CO₂



... et aussi de bois, de tissu,
de plastique

Le laser est un outil universel



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Le laser c'est...

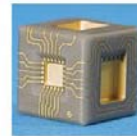
Dans l'industrie (suite)

Perçage

Laser YAG ou CO₂



Trous de 10 µm dans un film en polymères



Usinage

Supports en céramique pour microélectronique



Petites pièces mécaniques

Soudage



Réservoir de carburant pour fusée

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Le laser c'est...

Pour stocker l'information et la lire



Lecture de code-barres

Lasers à semi-conducteurs

CD et DVD



CD	DVD	Blu-ray Disc
$\lambda = 780 \text{ nm}$ $\text{NA} = 0.45$ 1.2 µm subpits	$\lambda = 650 \text{ nm}$ $\text{NA} = 0.6$ 0.8 µm subpits	$\lambda = 405 \text{ nm}$ $\text{NA} = 0.85$ 0.3 µm subpits

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Le laser c'est...

Pour transporter l'information



Le réseau mondial sous-marin de câbles de fibres optiques



On peut coupler les lasers avec des fibres optiques qui guident la lumière pendant des milliers de km

Les pertes à grande distance sont plus faibles que celles qu'on a pour un signal électrique dans un conducteur métallique



80% des communications à longue distance dans le monde le sont grâce au réseau de fibres optiques

Le multiplexage (superposition de signaux de différentes fréquences) permet d'avoir jusqu'à 256 canaux par fibre et d'augmenter le débit

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Le laser c'est...

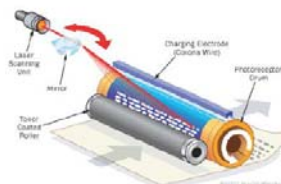
Au bureau ou à la maison

Imprimante laser

Le toner se colle au tambour au niveau du spot laser

Il est ensuite déposé sur la feuille de papier

Grâce au laser, vitesse et la résolution sont meilleures qu'avec un jet d'encre



Particule de toner

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Le laser c'est...

Dans le bâtiment (suite)

Nettoyage de la pierre des monuments et des sculptures :
sans eau, sans produit chimique, sans abrasif, sans pression



Façade de la cathédrale Notre Dame de Paris

Laser YAG pulsé

Restauration du Musée national
du Moyen Age



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Le laser c'est...

Le laser Mégajoule

En construction par le CEA au CESTA près de Bordeaux,
il sera avec le NIF à Livermore le laser le plus énergétique au monde



Un hall de 320 m de long (40 000 m²)
maquette

La cible : une microbille au
centre d'une chambre
d'expérience de 10 m de
diamètre



240 faisceaux synchronisés entre eux,
durée de l'impulsion 20 ns, YAG 1053 nm amplifiés puis triplés en fréquence → UV
L'énergie produite à chaque impulsion sera de **1,8 MJ**
focalisée sur moins de 1mm²
Puissance crête **550 TW**

Fonctionnement prévu en 2014

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Mais le Laser c'est aussi...

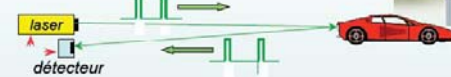
Mesurer des distances ou des vitesses



Télémètre laser

Laser en impulsions

Mesure de distance : temps mis par la lumière pour faire un aller-retour
 en plus des radars, les "jumelles laser"



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Et aussi...



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Et Malheureusement aussi...



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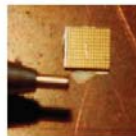
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Une grande variété de lasers...

Une grande variété de réalisations et de propriétés

• Géométries et dimensions

100 microlasers
à semiconducteur



Laser Nova pour la fusion nucléaire

• Puissances

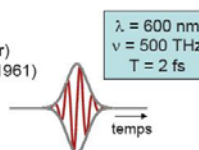
du microwatt au pétawatt ($1\text{PW} = 10^{15}$ watts)

• Continus ou pulsés

Des impulsions de plus en plus courtes :

- fonctionnement relaxé (le premier laser)
- fonctionnement déclenché (Q-switch, 1961)
- blocage de modes

Impulsions femtosecondes ($1\text{fs} = 10^{-15}\text{s}$)



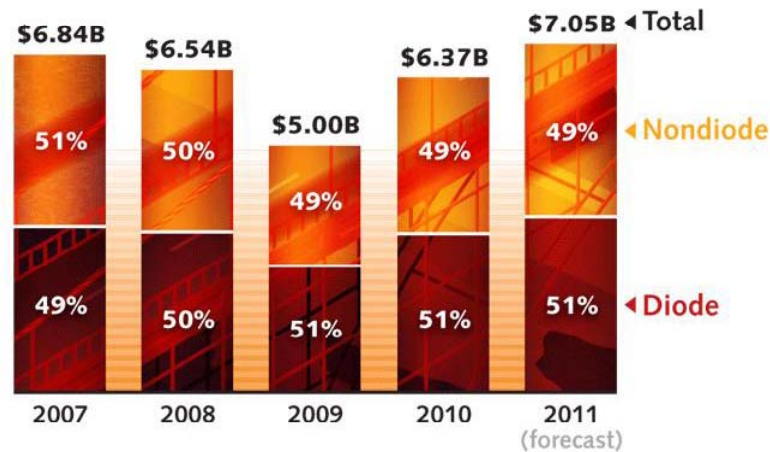
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Le laser, quelques données commerciales...

Worldwide commercial laser revenues



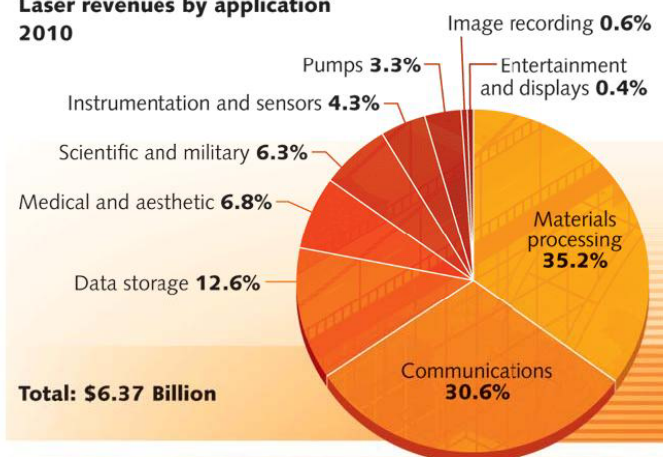
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Le laser, quelques données commerciales...

**Laser revenues by application
2010**

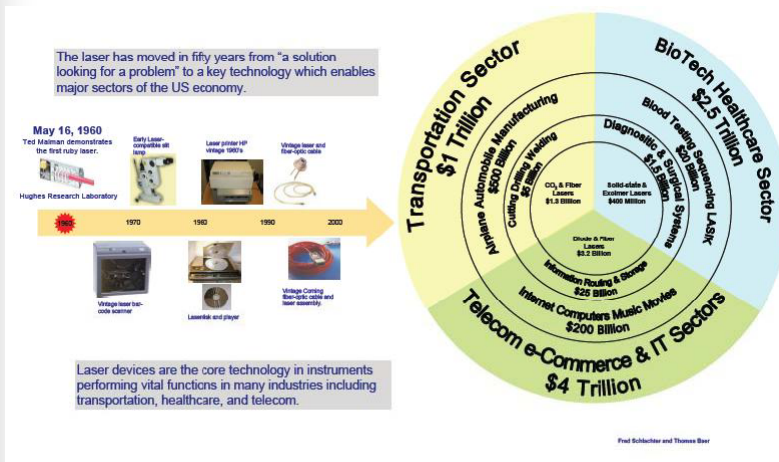


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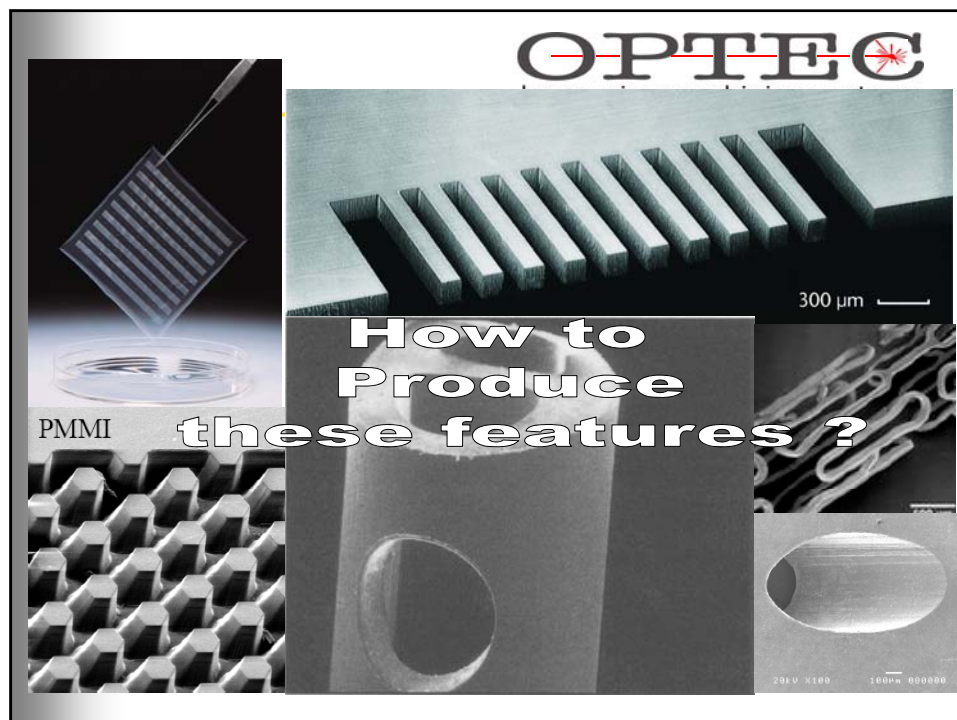
Le laser est un composant dans la chaîne ...



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Why use lasers at all?

• Conventional

- EDM
- Mechanical
- Chemical milling
- Water jet
- Ion milling
- EB
- Plasma
- Punching
- Others...

• Laser

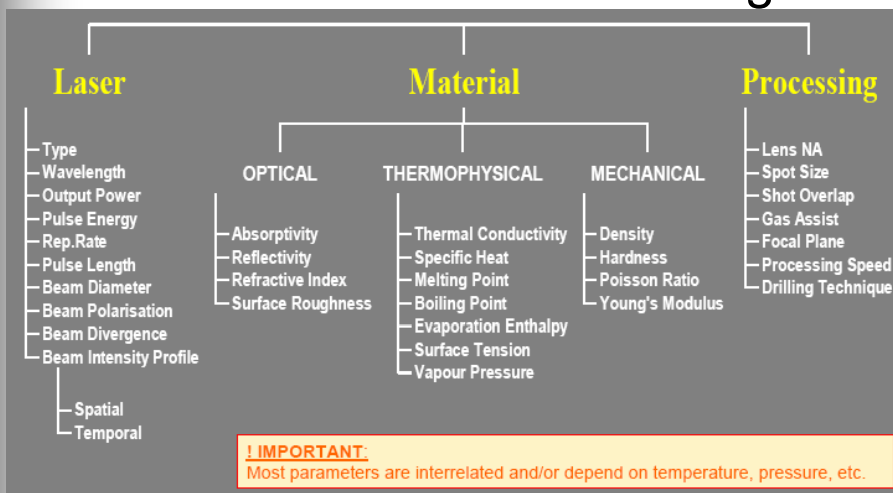
- Non Contact
- No Chemicals
- Selectivity
- Processing Speed
- High Resolution
- Flexibility
- Compactness
- Cost effectiveness

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Laser Materials Processing



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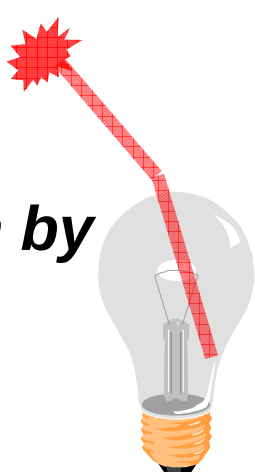
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Laser

- Type
- Wavelength
- Output Power
- Pulse Energy
- Rep. Rate
- Pulse Length
- Beam Diameter
- Beam Polarisation
- Beam Divergence
- Beam Intensity Profile
- Spatial
- Temporal

Light Amplification by Stimulated Emission of Radiations

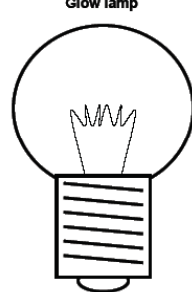


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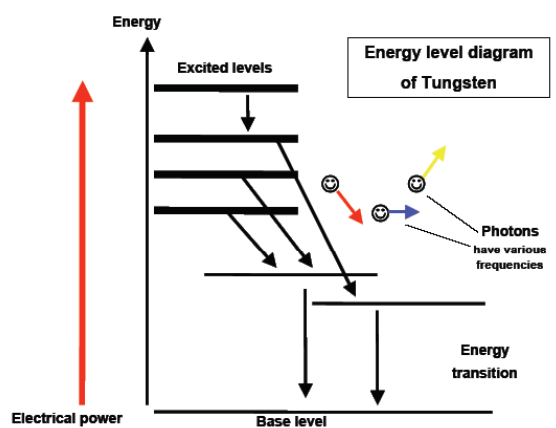
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Lamp / Laser

Spontaneous emission:



Glow lamp



Energy level diagram of Tungsten

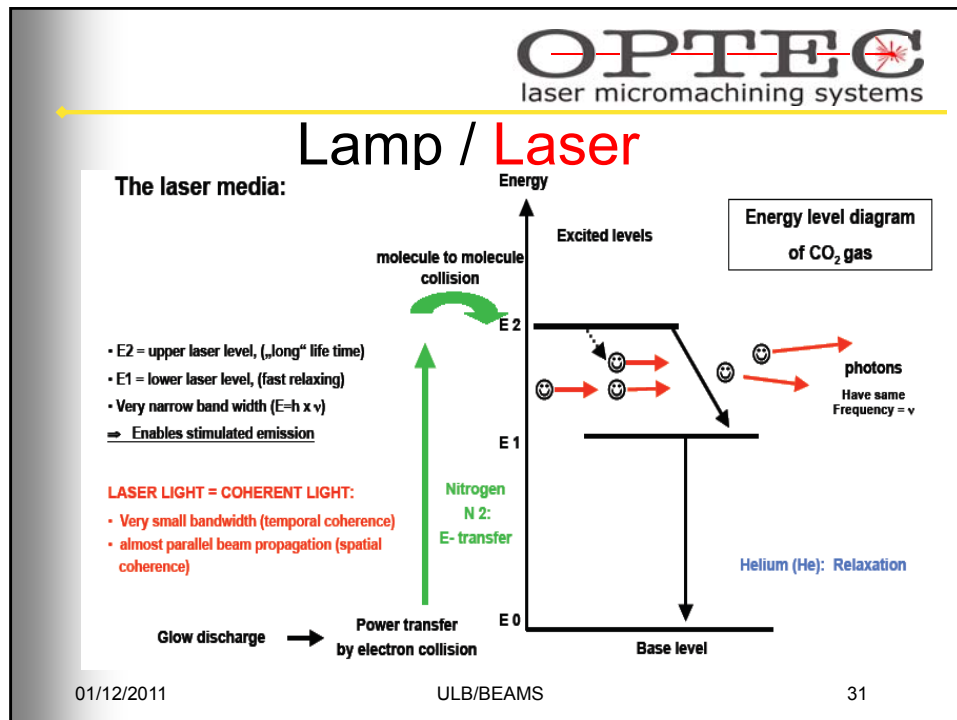
Photons have various frequencies

Energy transition

Base level

Electrical power

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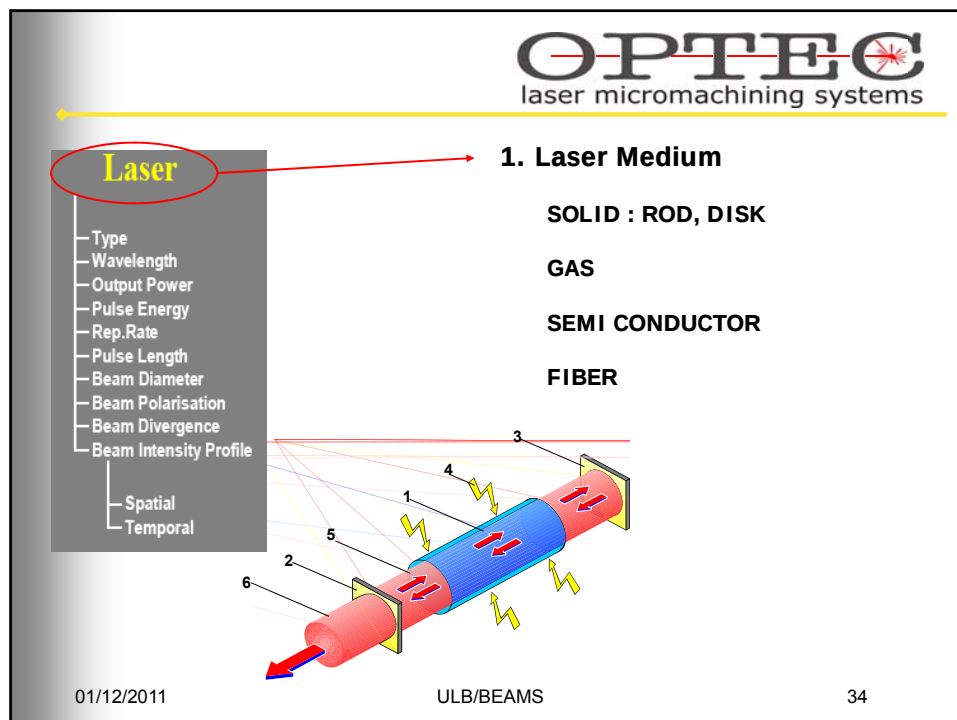
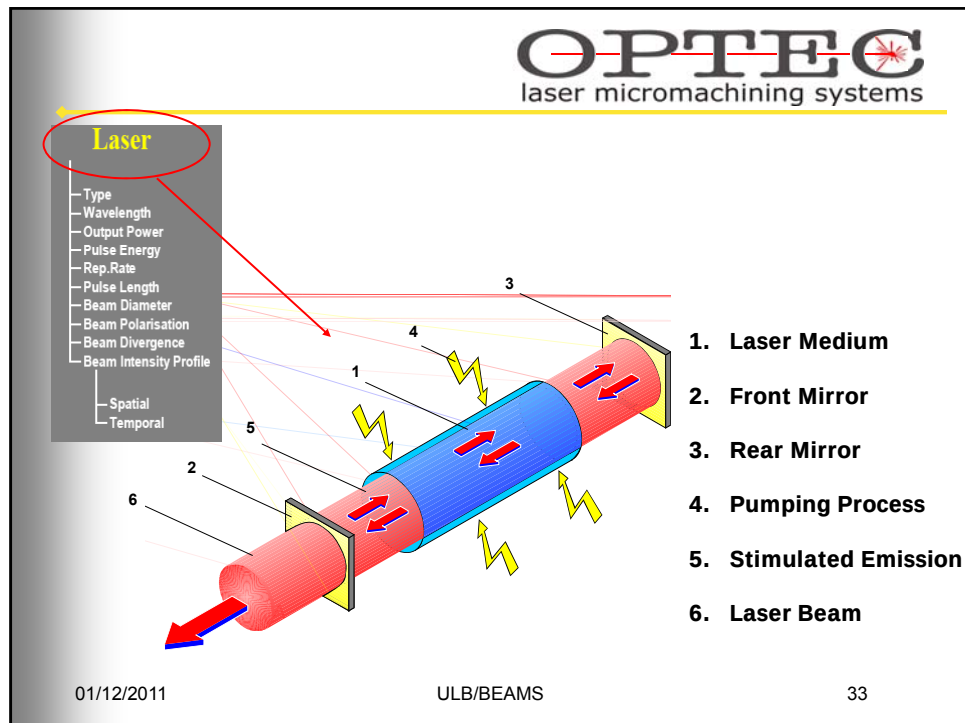
What is a LASER ?

- A LASER is a device which generates or amplifies light.
- Properties of laser beams:
 - Monochromatic
 - Directional
 - Coherent
 - Intense

Laser

- Type
- Wavelength
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Laser

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4. Pumping Process

Electrical Discharge

Flash Lamp

Diode Laser

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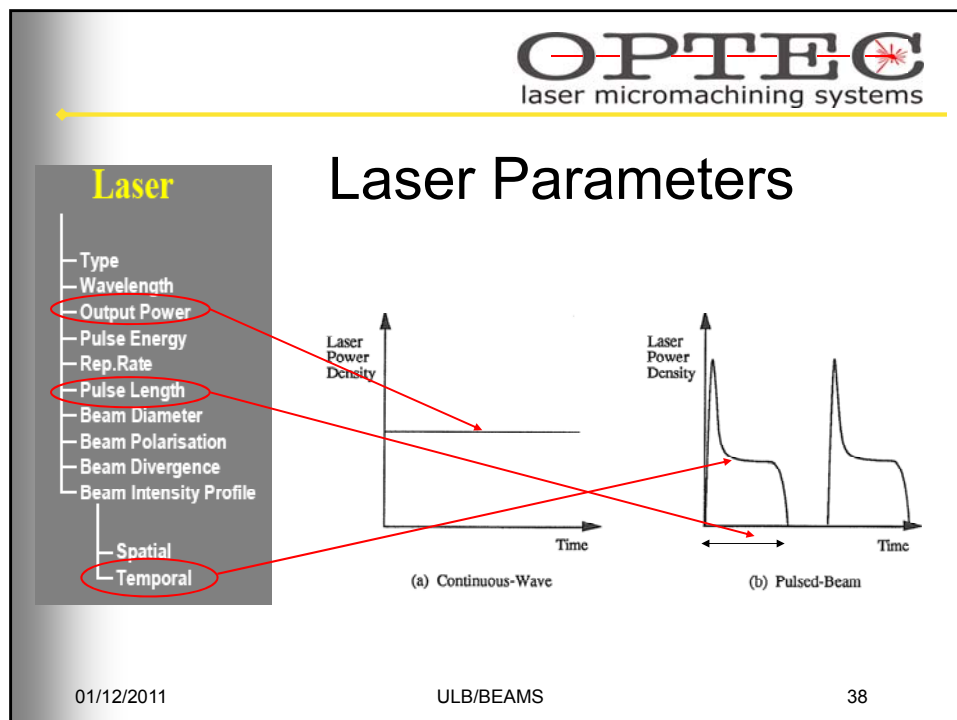
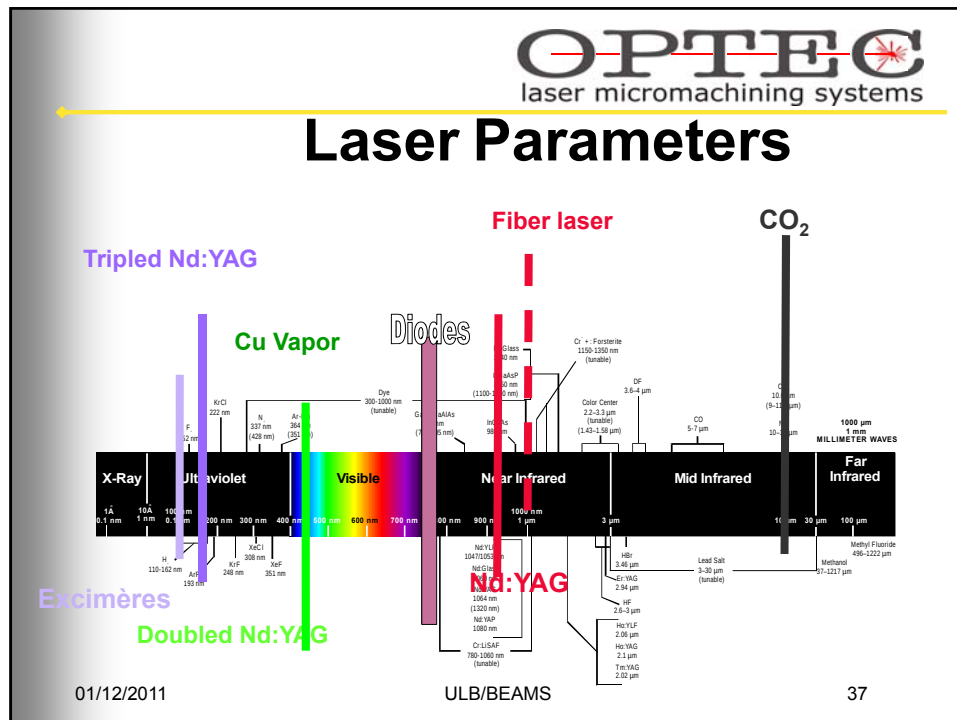
Laser

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Laser Parameters

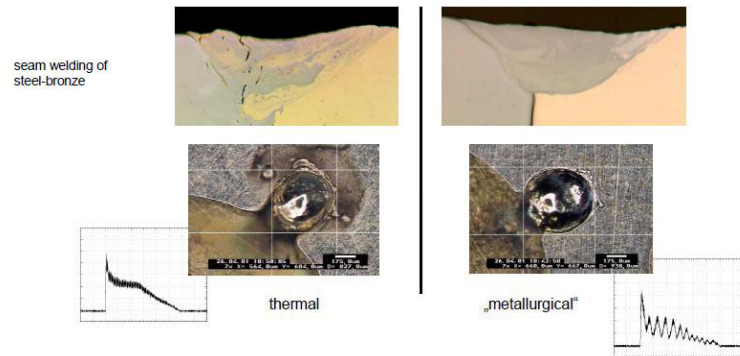
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Laser Parameters

„metallurgical“ adaption of the laser pulse

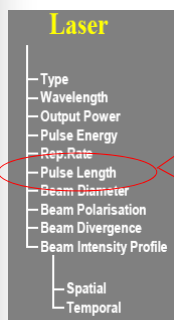


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Laser Parameters



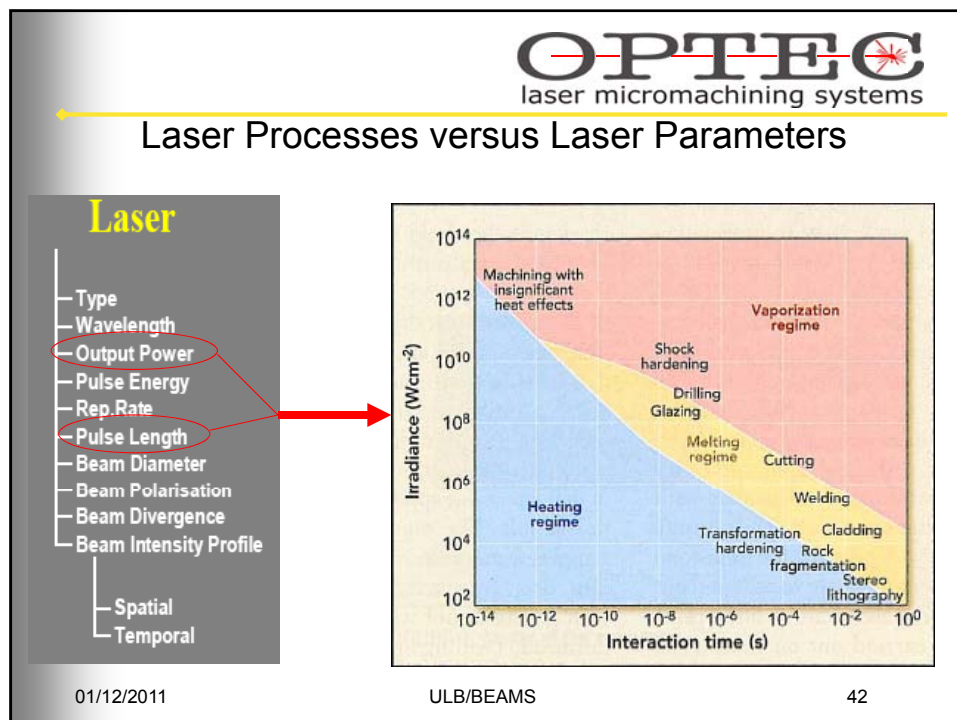
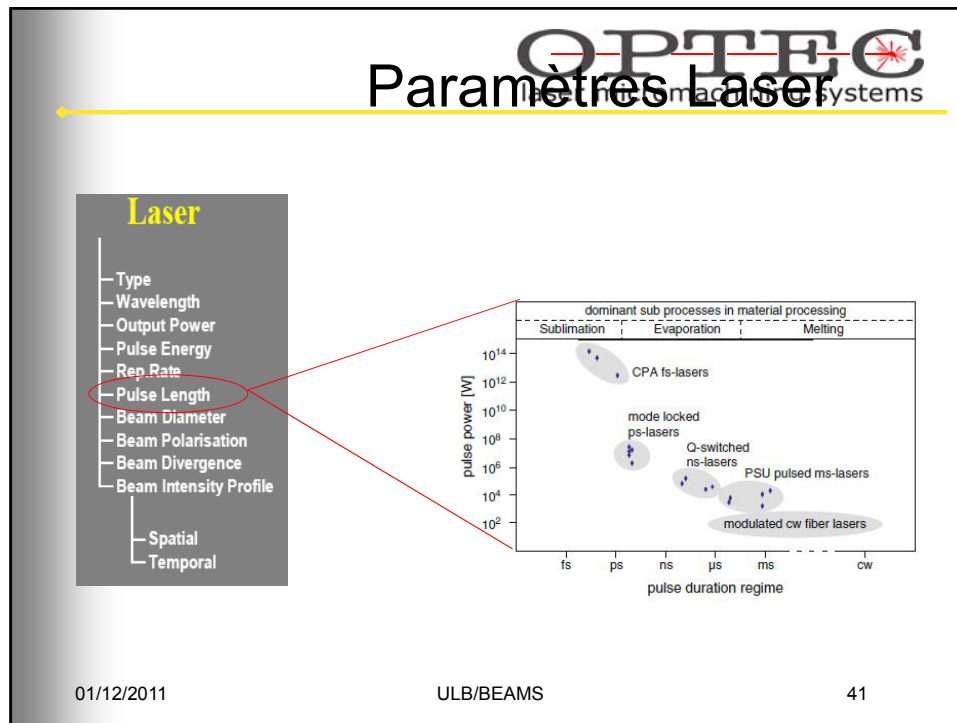
- Pulse length (*):
 - Millisecond (ms)
 - Microsecond (μ s)
 - Nanosecond (ns)
 - Picosecond (ps)
 - Femtosecond (fs)

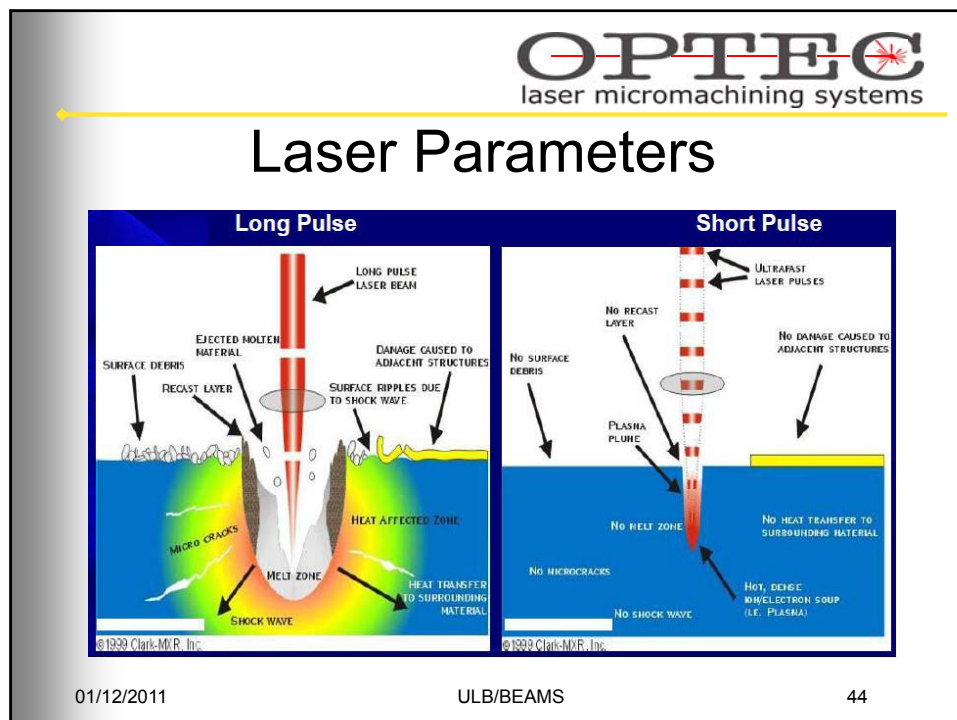
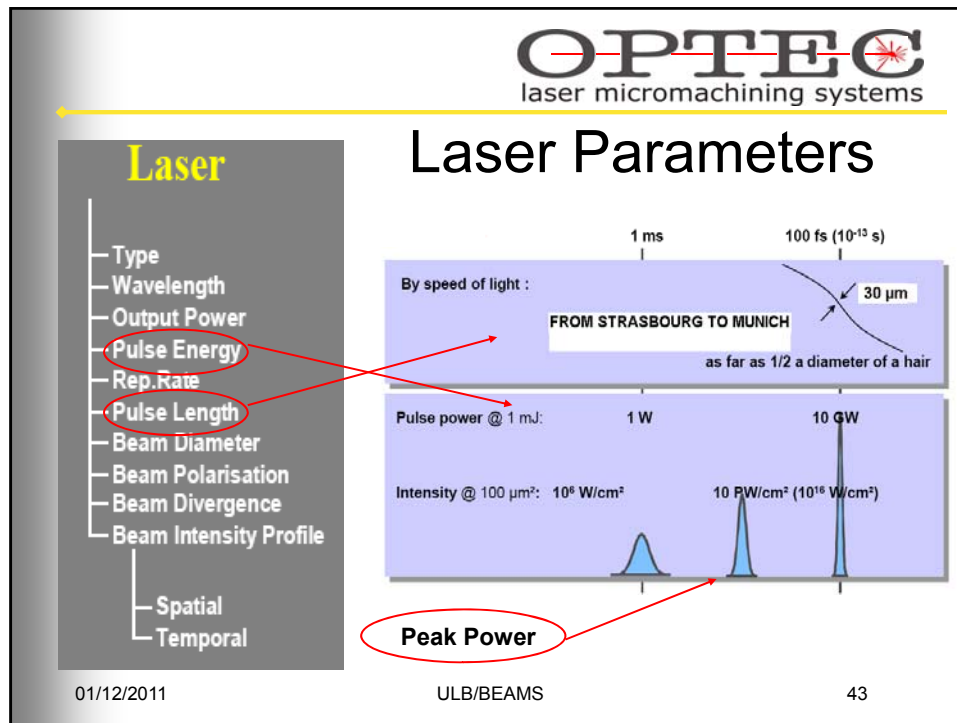
(*): time scale considered for
 μ machining

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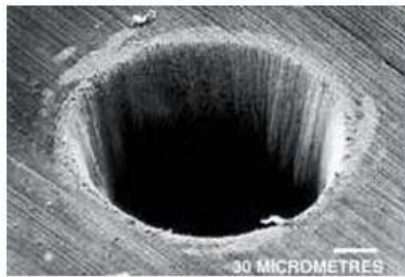
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Laser Parameters



$t = 200$ femtosecondes



$t = 3.2$ nanosecondes

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LASERS...

LASER	MEDIUM	Wavelength (nm)	Pulse width	PRF
DPSS	Solid	213 - 1064	ns - μ s	1 Hz - 200 kHz
CVL	Gas	255, 511	ns	kHz
Excimer	Gas	157 - 351	ns	1 Hz - 1 kHz
Ultrafast	Solid	390 - 1048	fs - ps	1Hz - 10 MHz
Fiber	Fiber	1057	ps - ns	1Hz - 100 kHz
CO2	Gas	9000 - 11000	ns - μ s	1 Hz - 100 kHz

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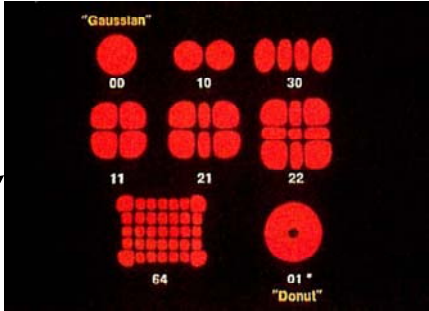
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Laser Parameters

Laser

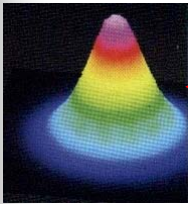
- Type
- Wavelength
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- Beam Diameter
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 - Temporal



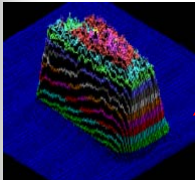
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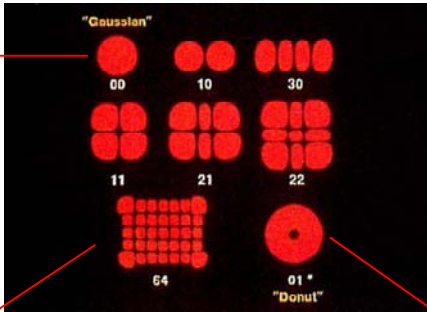
Laser Parameters

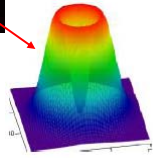


Gaussian



Multimode





Donut

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Laser Parameters

Laser

- Type
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- Pulse Length
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- Temporal

Tailored PulsesTrains

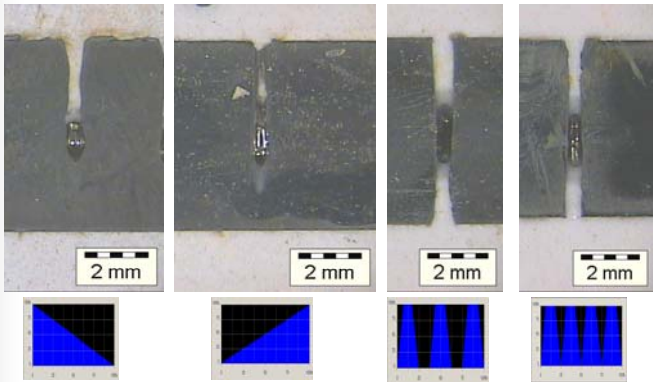
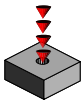
A new Process?

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Special laser solutions for super alloy hole drilling

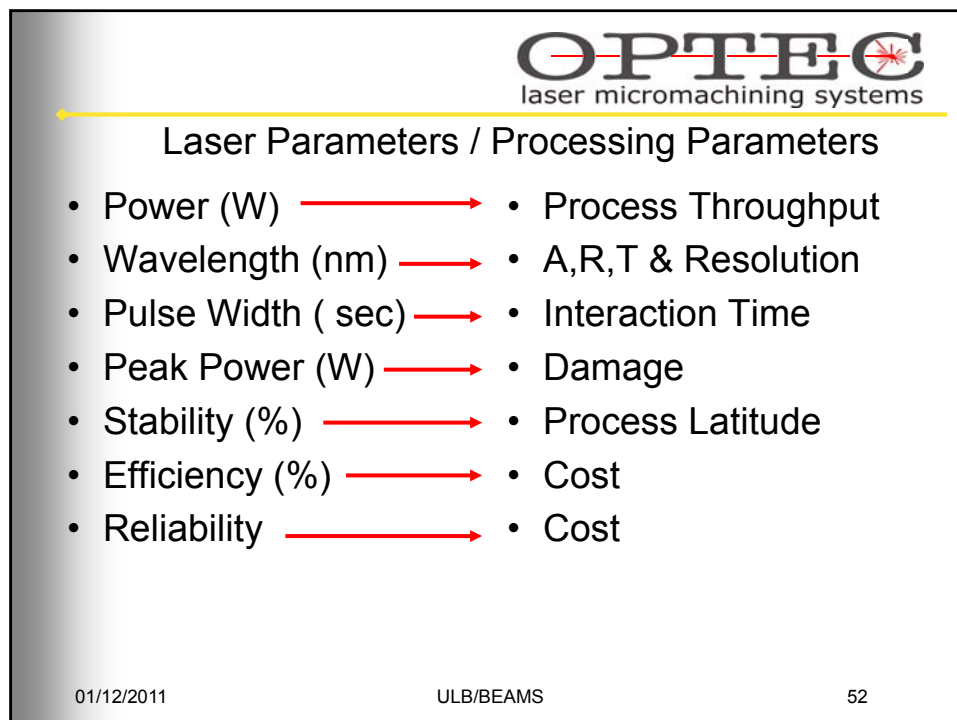
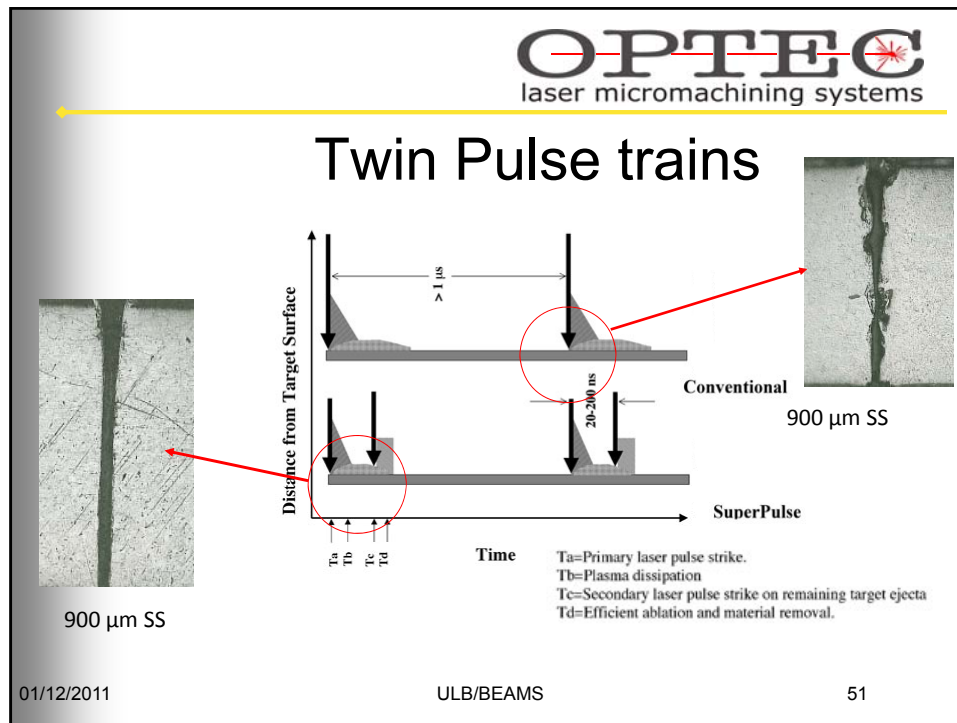
R&D: Drilling with pulse shaping technique

Pulse length: 2.8ms
Peak power: 8.5 kW
20 pulses (5Hz, 12.9J)

thickness: 6mm
Fiber core diameter: 0.4mm
Material: 1.4301

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Laser Parameters / Processing Parameters

The Balance

BUT WHAT ABOUT COST?

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Material Optical Properties

OPTICAL

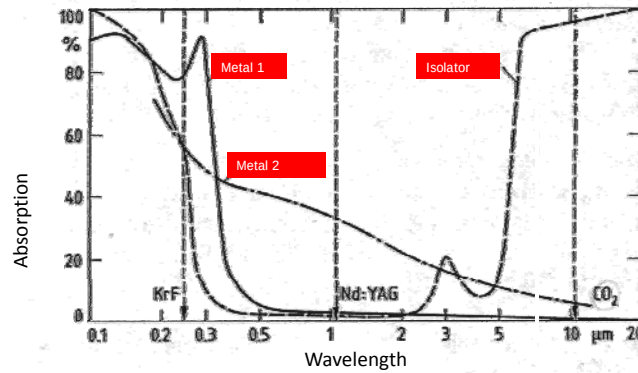
- Absorptivity
- Reflectivity
- Refractive Index
- Surface Roughness

→

- $A + R + T = 100 \%$
- A : Absorption
- R : Reflectivity
- T : Transmission
- Depends on Temperature

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Material Optical Properties...



Metal 1: Au, Ag, Cu..., Metal 2: Fe, Ni, Cr...,
Isolator: glass, Polymer

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OPTICAL

- Absorptivity
- Reflectivity
- Refractive Index
- Surface Roughness

Laser

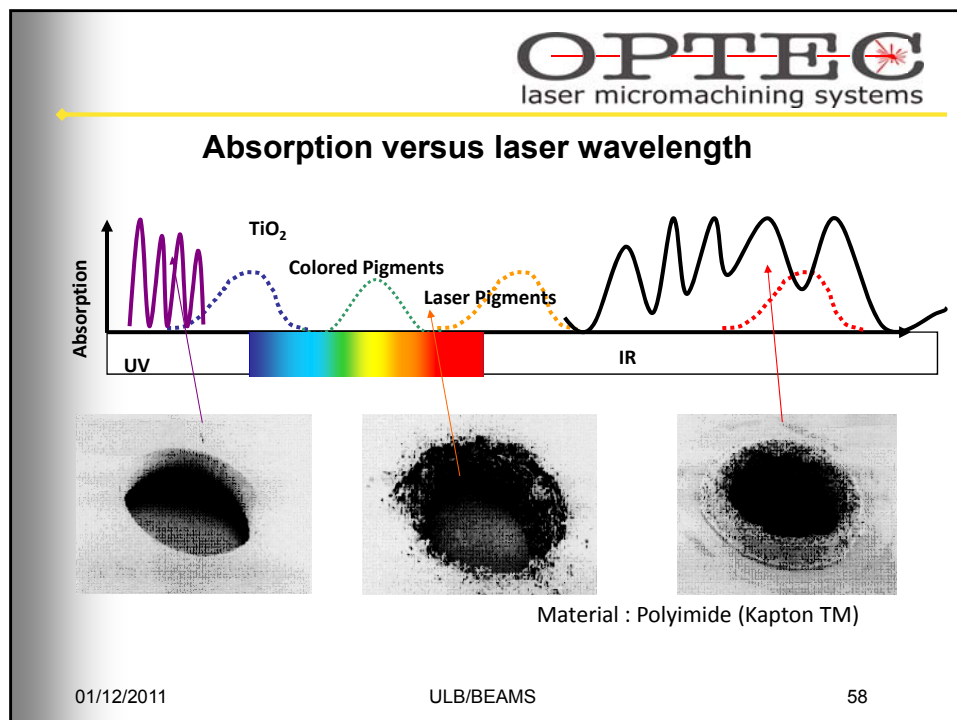
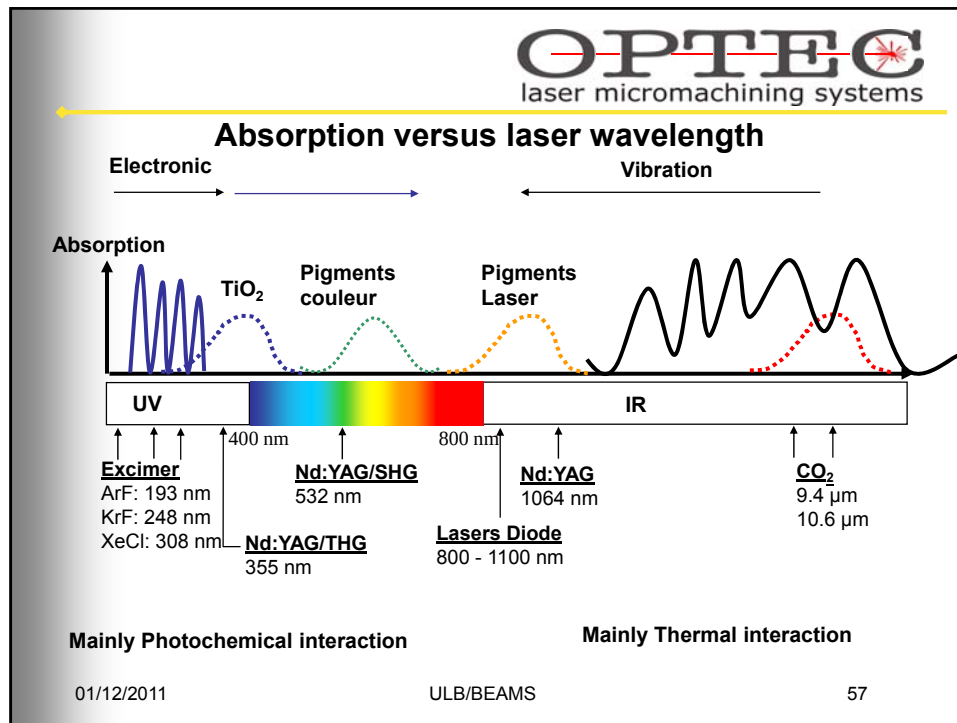
- Type
- Wavelength

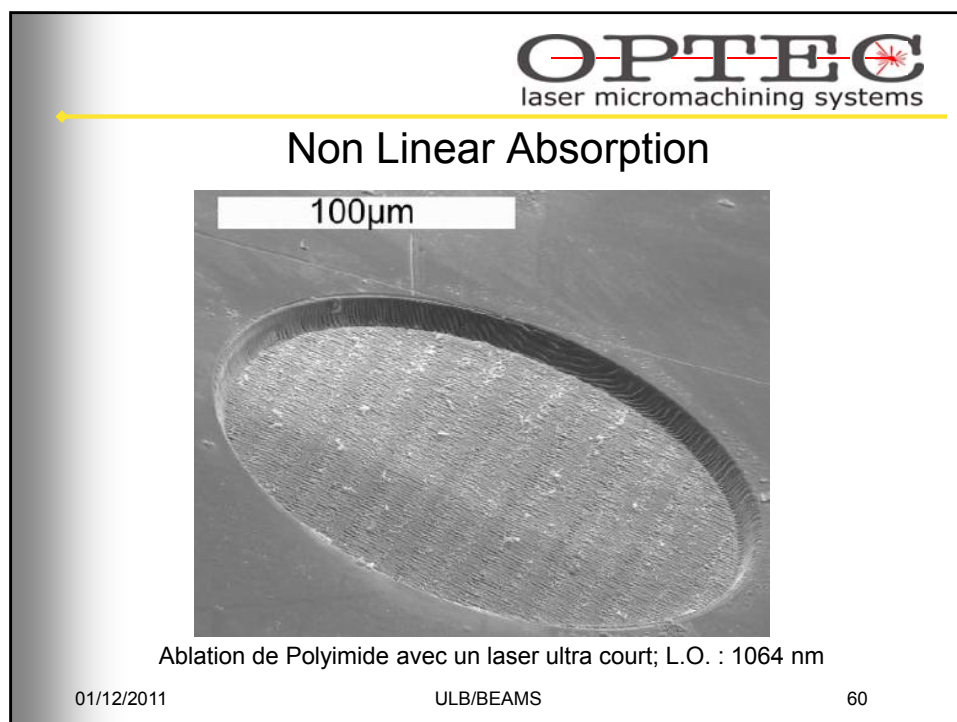
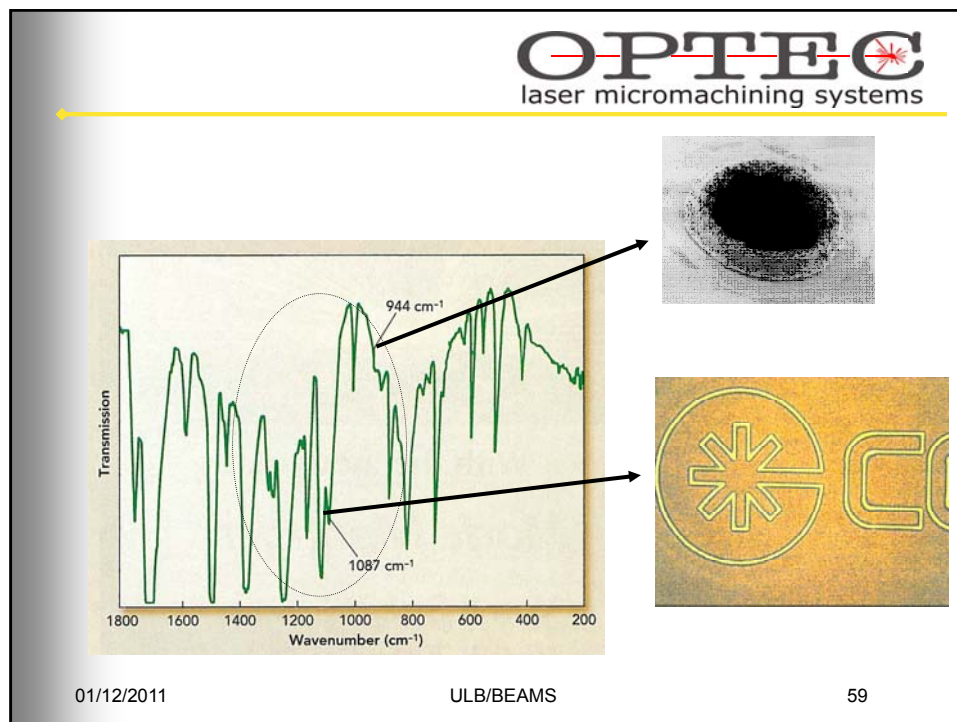
Metal	At 10.6 μm	At 1.06 μm	At 0.25 μm
Aluminum	2	10	18
Iron	4	35	60
Copper	1	8	70
Molybdenum	4	42	60
Nickel	5	25	58
Silver	1	3	77

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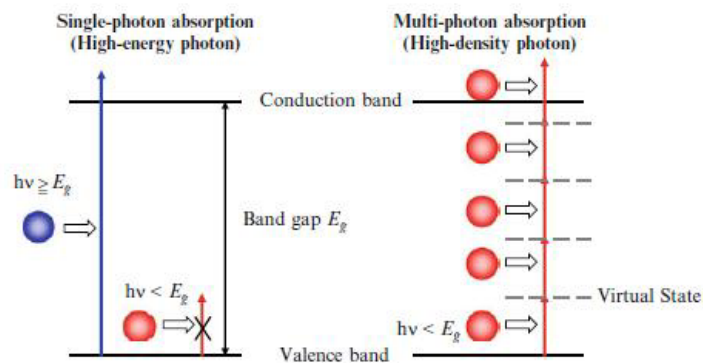
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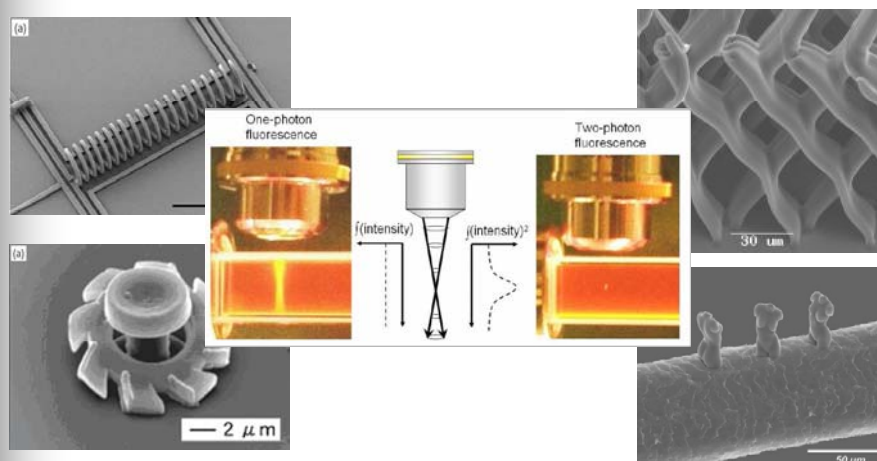
Non Linear Absorption: Multiphoton effect



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Materials Properties

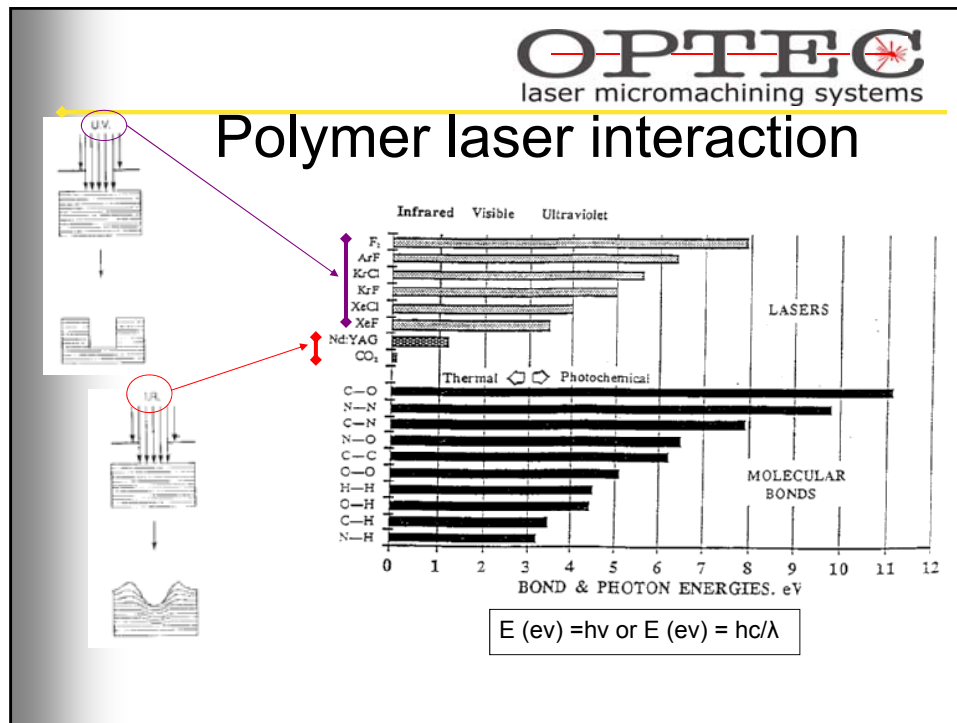
THERMOPHYSICAL

- Thermal Conductivity
- Specific Heat
- Melting Point
- Boiling Point
- Evaporation Enthalpy
- Surface Tension
- Vapour Pressure



- Metals
- Ceramics
- Polymers
- Glass
- Composites

POLYMER LASER INTERACTION



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UV + Short pulse = Precision micromachining:-

CHARACTERISTICS

- UV radiation (248nm or 193nm) strongly absorbed in nearly all materials
- Short (4-6ns) pulse duration

RESULT

- High energy density absorbed in surface layers, - efficient vaporisation with sub- μm depth precision
- Precision machining with minimum kerf and absence of thermal effects

Ablation
0.1-1.0 μm /shot

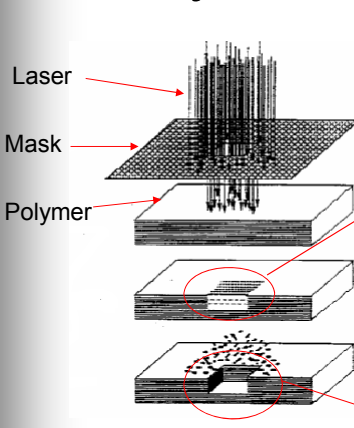
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Polymer laser interaction

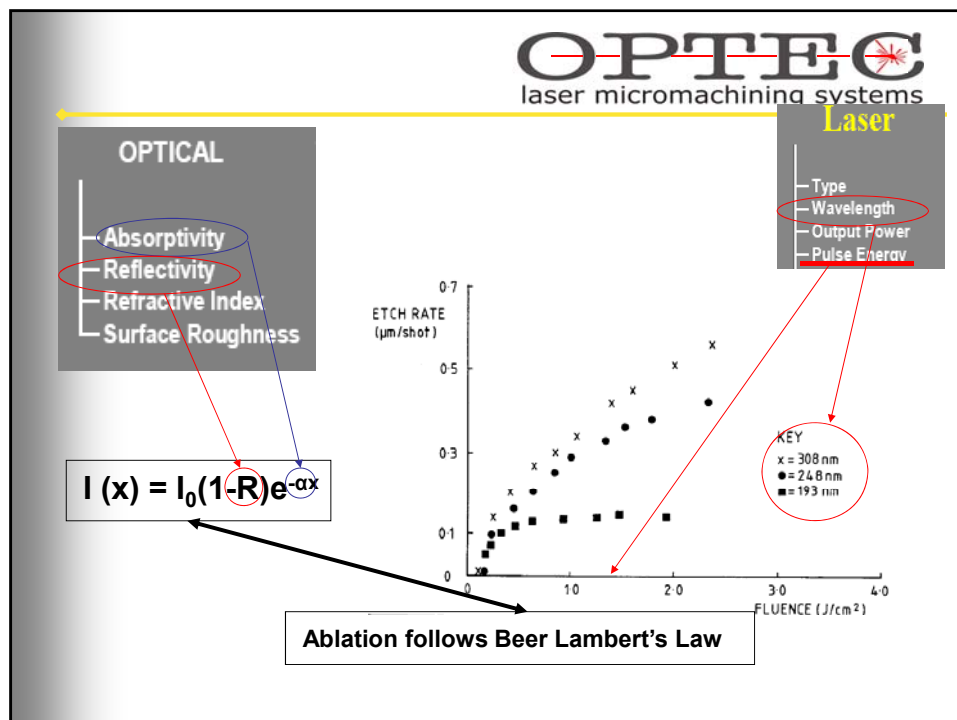


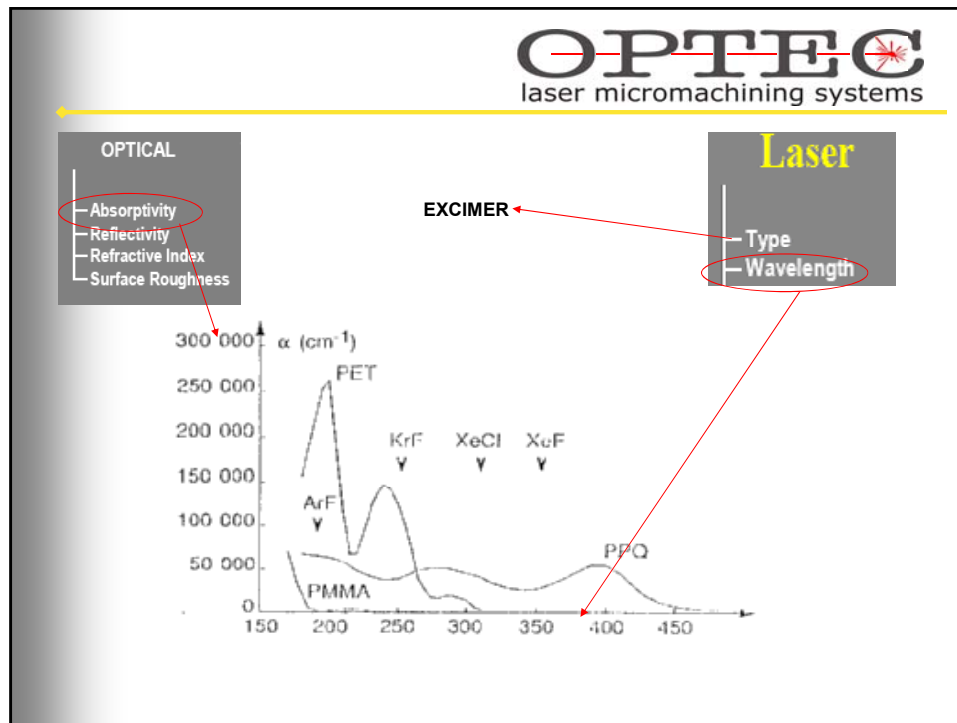
Laser
Mask
Polymer

Etching of polymers by non thermal cracking of bounds due to valence transitions induced by UV photons

PMMA

100 μm

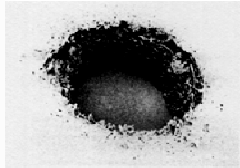
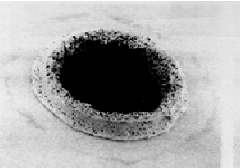
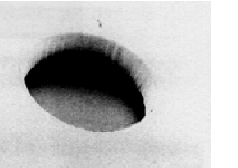




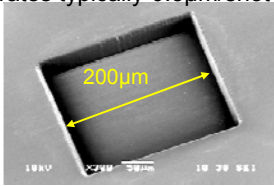
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laser micromachining systems

Photoablative decomposition in polymers:-

Nd-YAG (1.06 μm)	CO_2 (10.6 μm)	Excimer (0.248 μm)
------------------------------	-------------------------------------	--------------------------------

Unlike Nd-YAG or CO_2 lasers, excimer laser ablation of most polymers occurs by photo-ablative decomposition, with little excess heat and removal rates typically 0.3 $\mu\text{m}/\text{shot}$.



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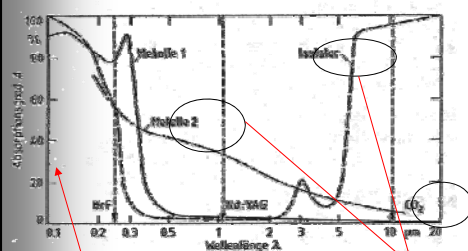
COMBINED MATERIALS LASER INTERACTION

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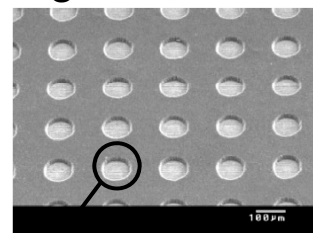
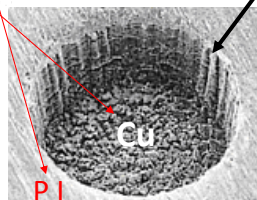
71

Absorption versus wavelength



OPTICAL

- Absorptivity
- Reflectivity
- Refractive Index
- Surface Roughness



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Laser Blind Vias Drilling

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Ablation threshold...

Exitech Limited

40um

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Selective machining, polymers from metals:-

Ablation Rate

Fluence

Polymer

Metal

SAW filters

Flex contacts

Humidity Sensor

Wire Strip

Implant

Stent

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laser micromachining systems

Processing

- Lens NA
- Spot Size
- Shot Overlap
- Gas Assist
- Focal Plane
- Processing Speed
- Drilling Technique

Laser Processing

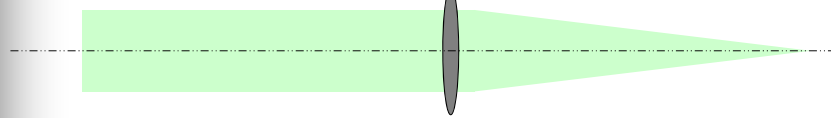
Direct writing

Projection

Others: Maskless, DOEs

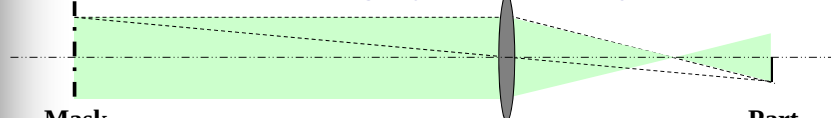
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Traditional lasers– focal point processing



Poor definition of focal point, low flexibility.

UV micromachining by pattern projection



Mask

Part

Precise definition on machined area by optical projection of mask image, many motif shapes possible.

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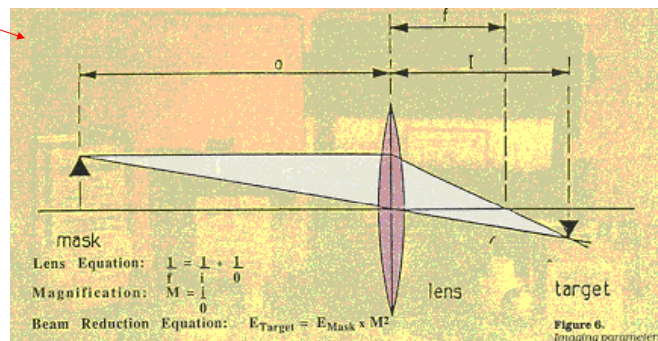
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Drilling Techniques / Projection

Processing

- Lens NA
- Spot Size
- Shot Overlap
- Gas Assist
- Focal Plane
- Processing Speed
- Drilling Technique



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laser micromachining systems

Drilling Techniques / Projection

Processing

- Lens NA
- Spot Size
- Shot Overlap
- Gas Assist
- Focal Plane
- Processing Speed
- Drilling Technique

- Static Mask and workpiece
- Moving Mask
- Moving Workpiece
- Synchronised Scanning
- Synchronised overlay scanning
- Bow Tie scanning
- Half Tone & Gray Scale Mask

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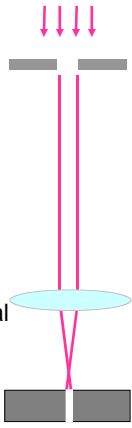
OPTEC
laser micromachining systems

Processing using simple motifs:- ...particularly suitable for small lasers!

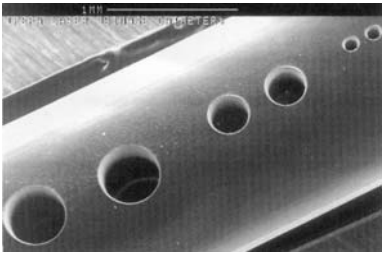
Laser illumination, generally around $50\text{mJ}/\text{cm}^2$

Mask, in this case with a single hole

Process lens to project mask image with typical demag. 4-20X
 $1-20\text{J}/\text{cm}^2$ on the part



- Drill/mill simple holes or shapes
- Drill many holes sequentially using X,Y part motion
- Use mask selector to change motifs, incl. alphanumeric
- For small features, energy requirements modest, but high rep. rate useful.



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Static Mask & Workpiece

50mJ/cm²

Typical demag. 4-20X

1-20J/cm²

- Drill simple holes or shapes
- Drill many holes sequentially using X,Y part motion or X,Y Galvo Scanners (also known as step & Repeat)
- Use mask selector to change motifs, incl. Alphanumeric (also known as indexed mask projection)

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Static Mask & Workpiece

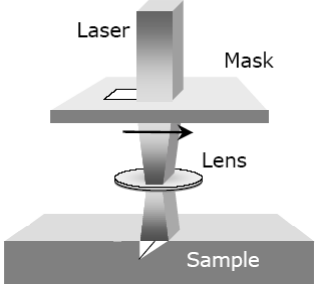
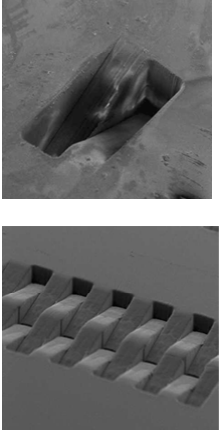
- Drill simple holes or shapes
- Drill many holes sequentially using X,Y part motion or X,Y Galvo Scanners (also known as step & Repeat)
- Use mask selector to change motifs, incl. Alphanumeric (also known as indexed mask projection)

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laser micromachining systems

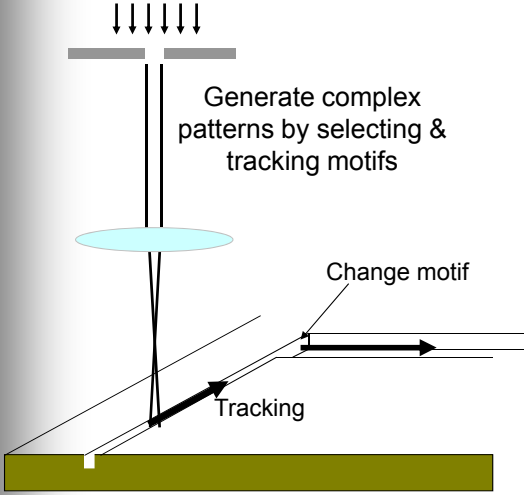
Drilling Techniques / Projection

Moving Mask

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laser micromachining systems

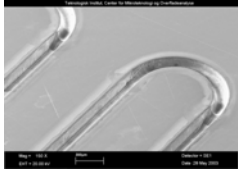
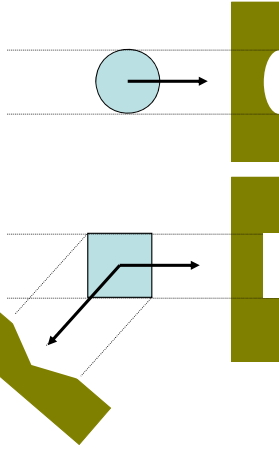


- Laser firing + motion generates a groove, or cuts through the part.
- For a given material, groove depth depends mainly on average shot dose (rep. rate x motif size/tracking speed)
- Use different motifs to generate complex patterns

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- tracked circle always makes elliptical-shaped profile, independently of direction

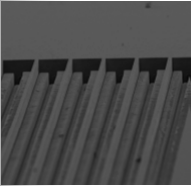
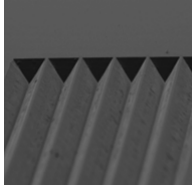
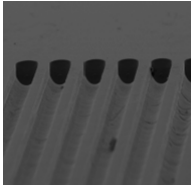
- For other shapes, profile depends on tracking direction

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Moving Workpiece...more

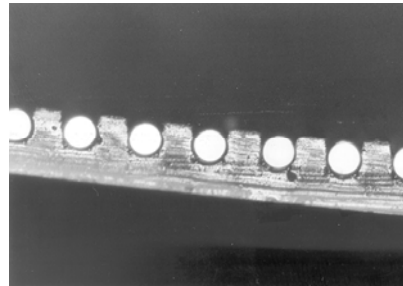
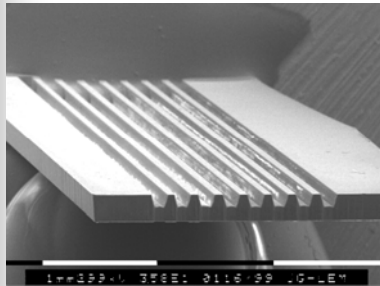
- Mask Shape:
 - T Mask
 - Triangle Mask
 - Round Mask

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Moving Workpiece

Microgrooving:some examples



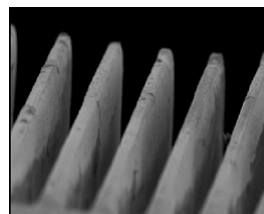
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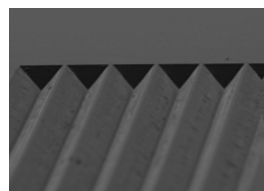
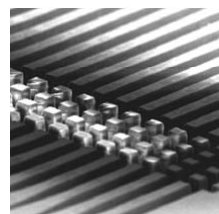
87

(INTEC - Ghent University - B)

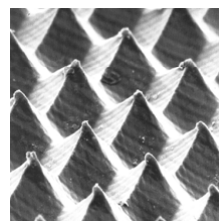
Moving Workpiece...more



→
Turn by 90°



→
Turn by 90°

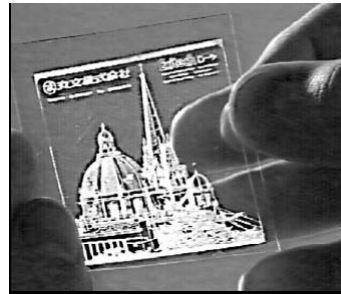
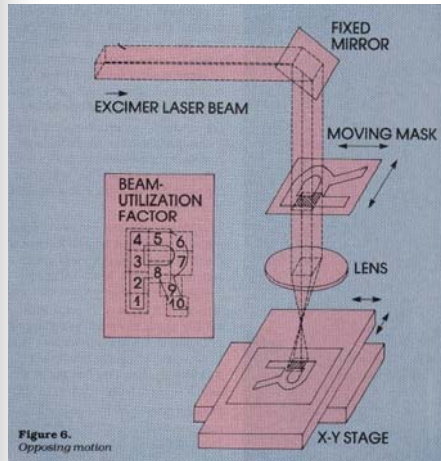


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Synchronised Scanning

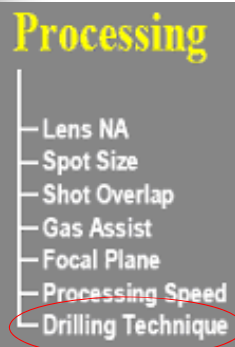


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Laser Processing



DIRECT WRITING

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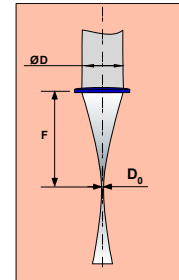
Drilling Techniques / Direct Writing

Processing

- Lens NA
- Spot Size
- Shot Overlap
- Gas Assist
- Focal Plane
- Processing Speed
- Drilling Technique

$$K = \frac{1}{M^2} = \frac{4 \lambda F}{\pi D_0 D} = \frac{4 \lambda}{\pi D_0 \theta}$$

$$D_0 = M^2 \times \frac{4 \lambda}{\pi} \times \frac{F}{D}$$

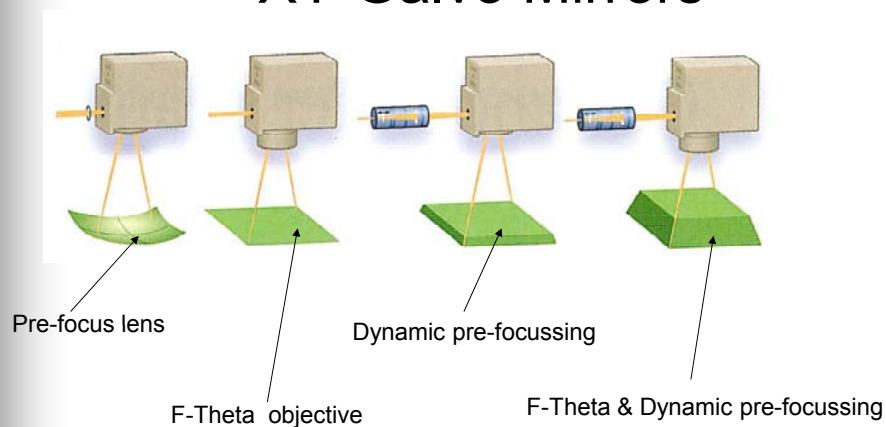


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XY Galvo Mirrors



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Drilling Strategies...Contd

single shot

percussion

trepanning

Helical drilling

Aspect (d/T)

Tolerance %

max. 1:15	max. 1:100	open	Source: HGSW Stuttgart open
5-10	5	5	<3

Pulsed Laser

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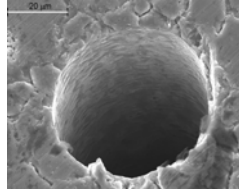
Drilling Techniques / Direct Writing

helical drilling

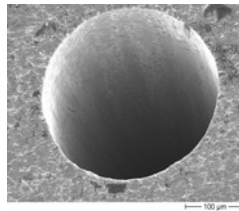
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Process Results

Material: stainless steel
Thickness: 1.2 mm
Diameter: $50\ \mu\text{m} \pm 2\ \mu\text{m}$
Time: 10 s



Material: stainless steel
Thickness: 1 mm
Diameter: $200\ \mu\text{m} \pm 3\ \mu\text{m}$
Time: 20 s



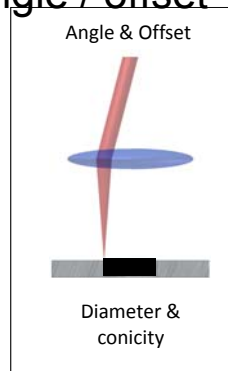
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Process Parameters...Contd

- Angle / offset



stainless steel
 $d=50\ \mu\text{m}$
depth=1 mm, $t=8\ \text{s}$



stainless steel
 $d=100/250\ \mu\text{m}$
depth 1 mm, $t=20\ \text{s}$

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Drilling Techniques / Others

Processing

- Lens NA
- Spot Size
- Shot Overlap
- Gas Assist
- Focal Plane
- Processing Speed
- Drilling Technique

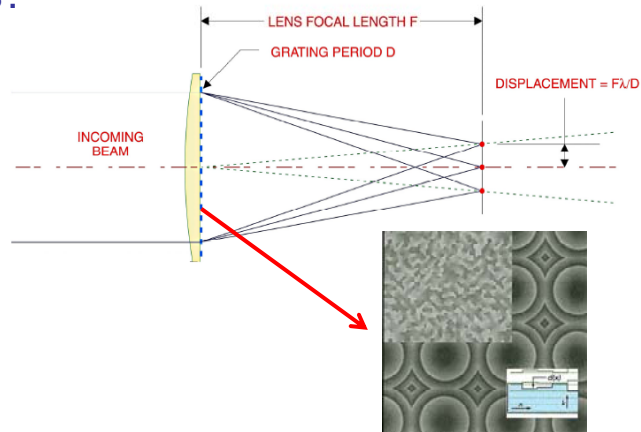
Maskless / Digital Mask

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Digital Masks:-

Mirror array

Drilling Techniques DOE's:-

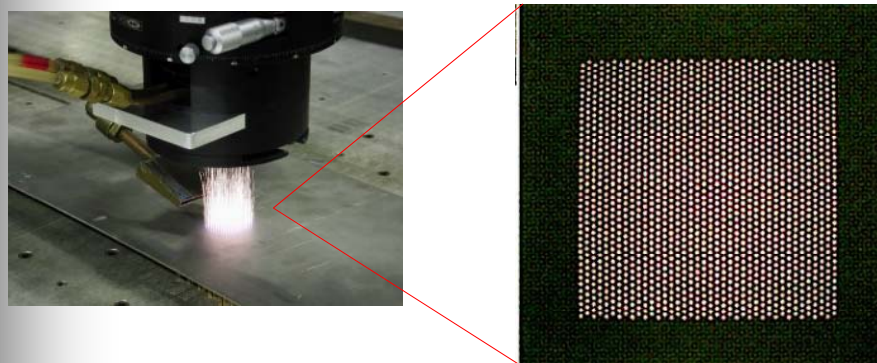


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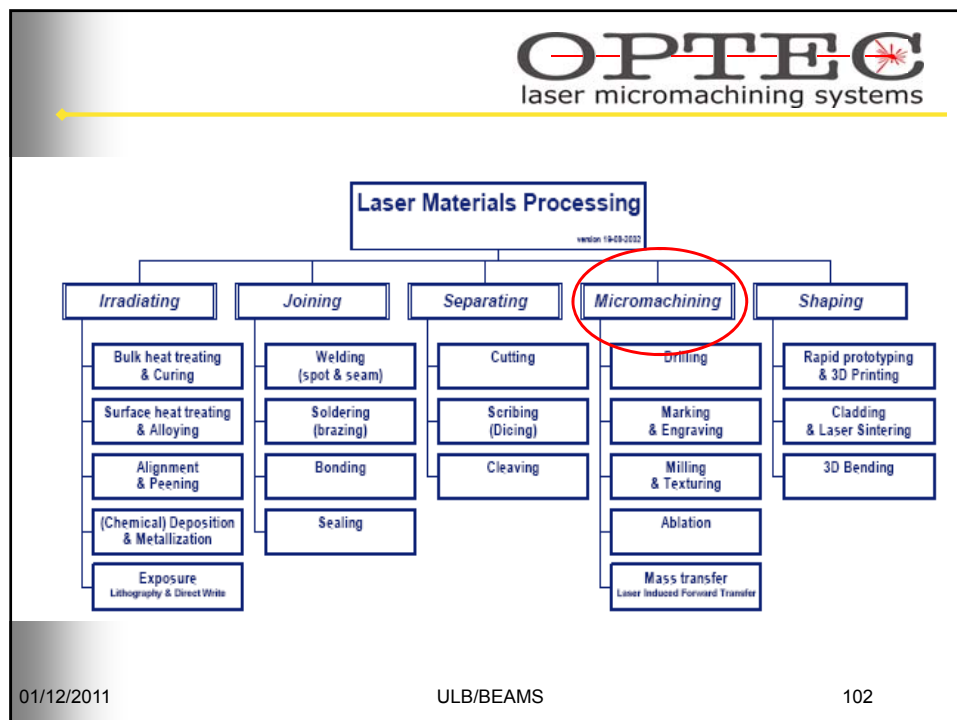
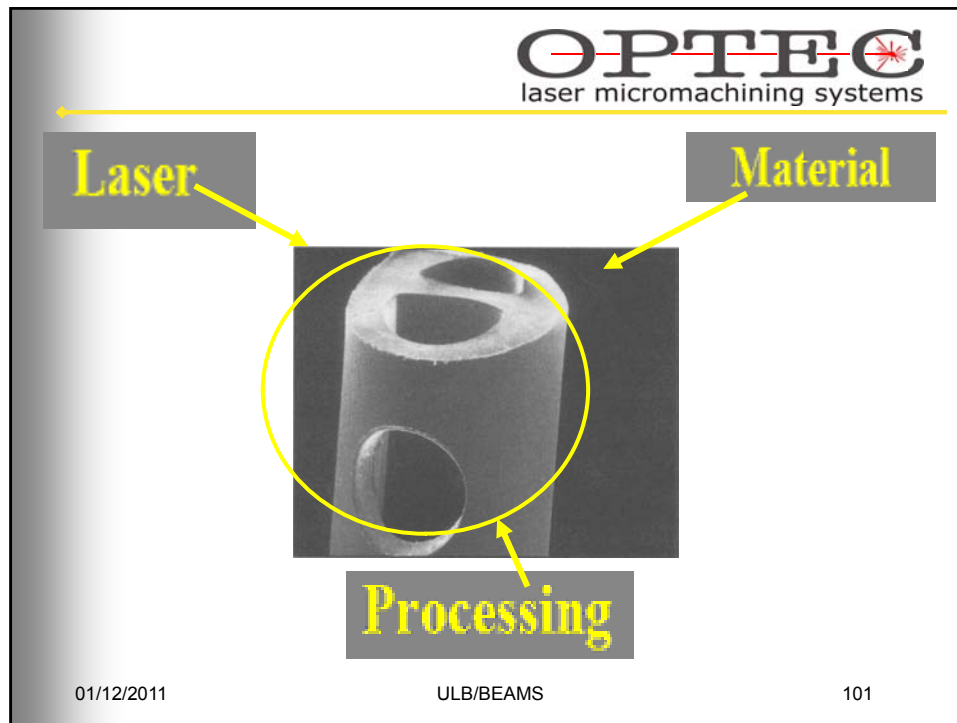
Drilling Techniques Many holes at once:-

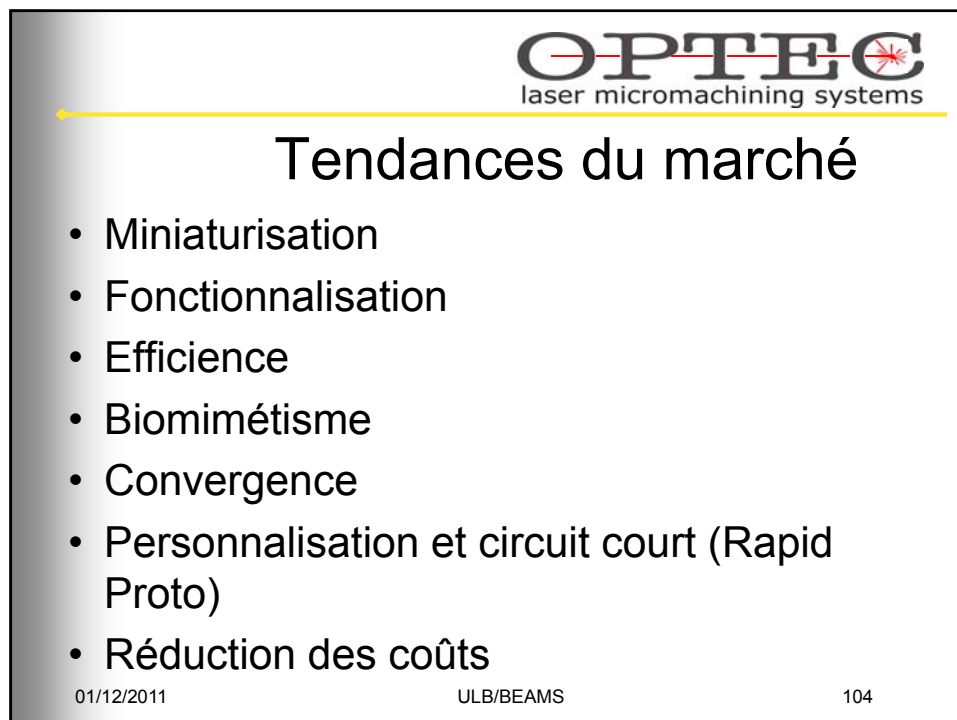
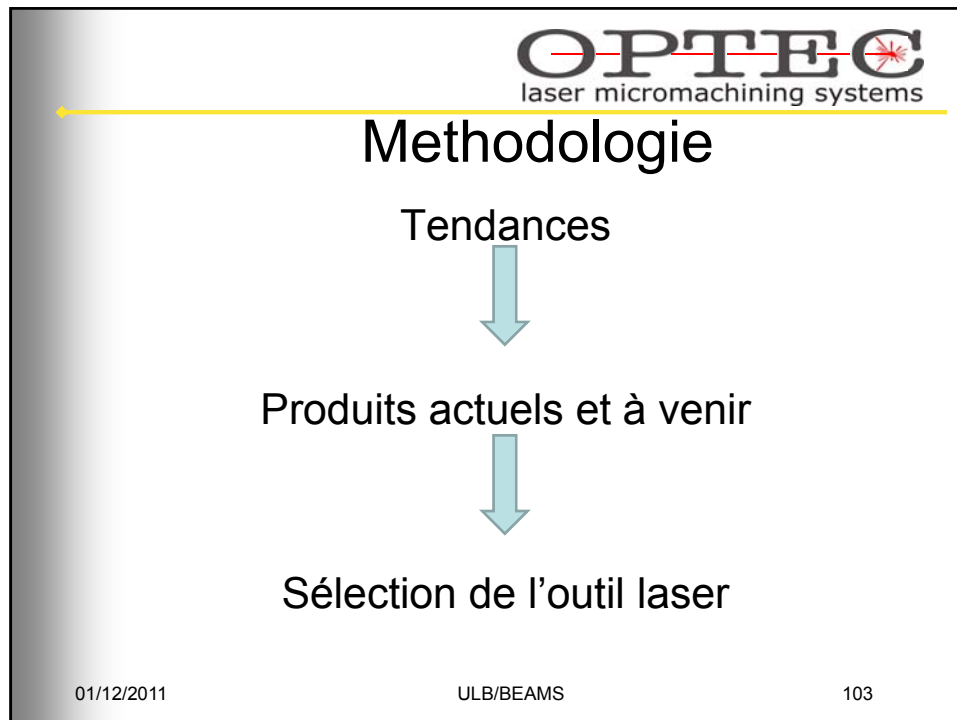


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Miniaturisation: Percage laser de micro-vie

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Miniaturisation...suite

HDD

Structure of suspension in HDD

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Fonctionnalisation

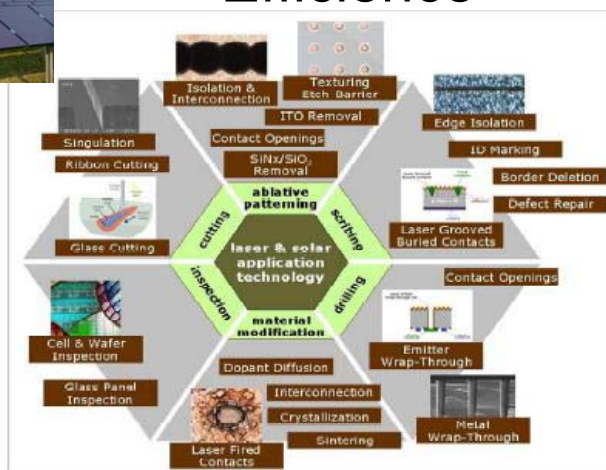


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Efficiency



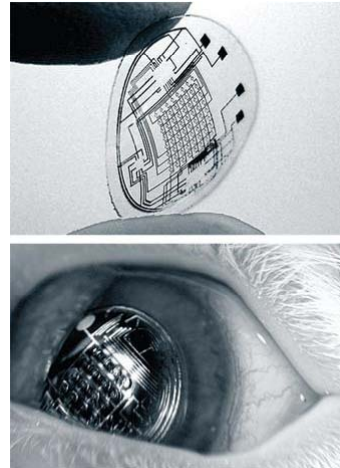
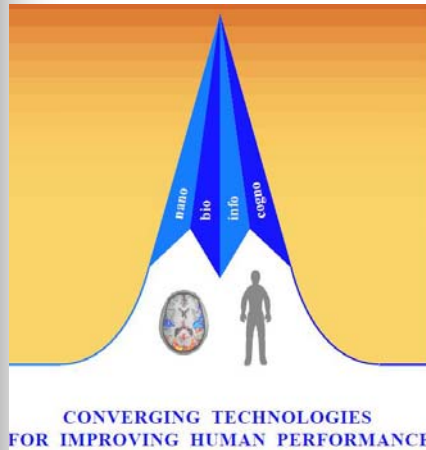
Classification of the different laser applications in solar by laser / material interaction process

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Convergence

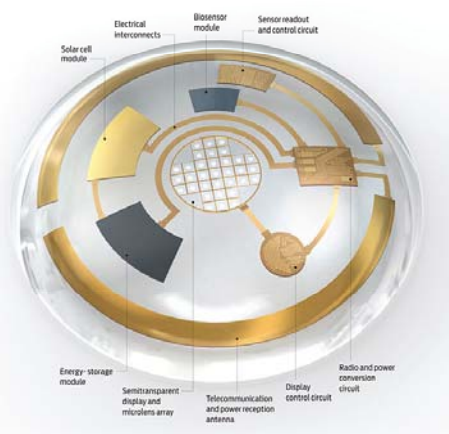
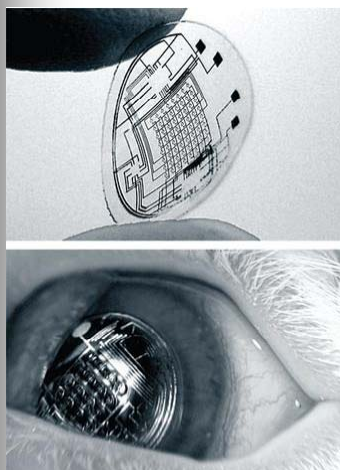


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Convergence...suite

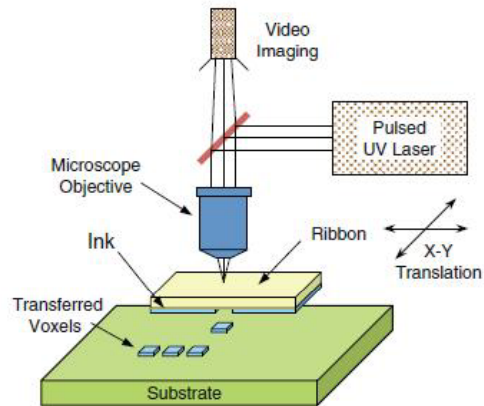
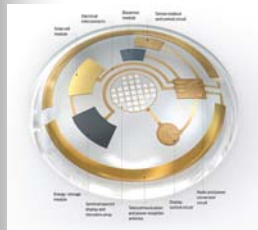


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Convergence...suite

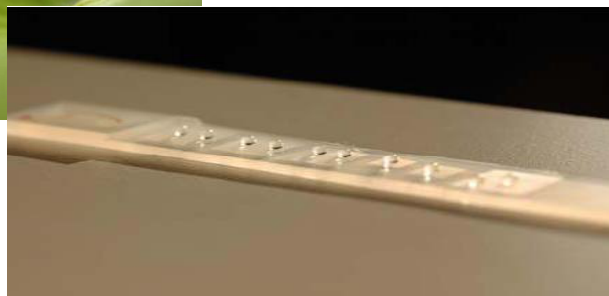


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Biomimétisme



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Biomimétisme...suite

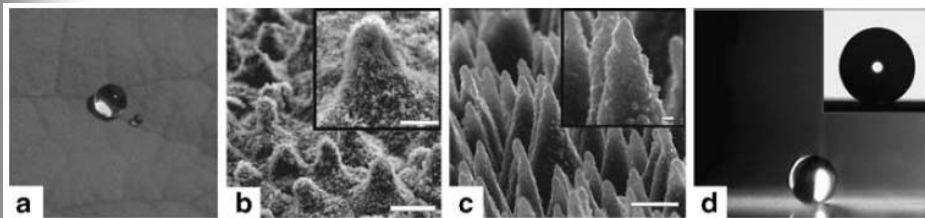


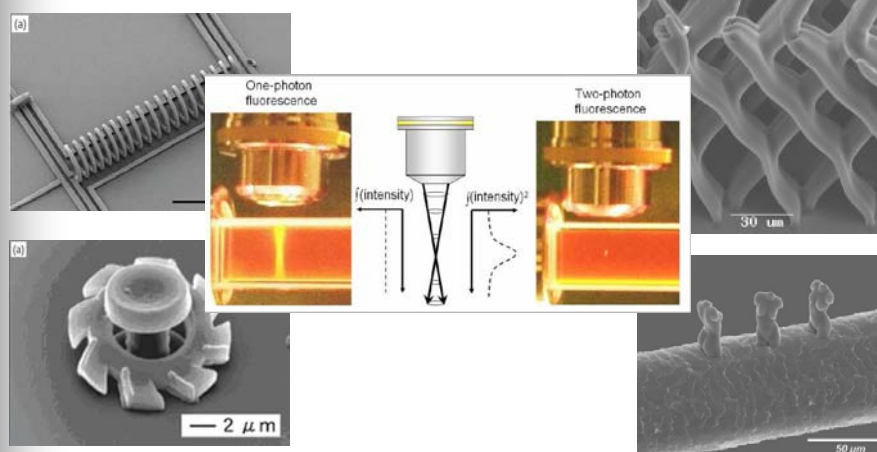
Fig. 4.5 (a) A bead of water on a lotus leaf [55]. (b) SEM image of the microscale (scale bar 10 μm) and *inset*: nanoscale structures (scale bar 5 μm) on the surface of a lotus leaf [56]. (c) SEM images of femtosecond laser textured Si surface showing microscale (scale bar 5 μm) and *inset*: nanoscale (scale bar 1 μm) structures [56]. (d) Image of a water droplet on a laser-structured, silane-coated, Si surface with a static contact angle of $\theta = 154 \pm 1^\circ$ [57]

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Construction additive



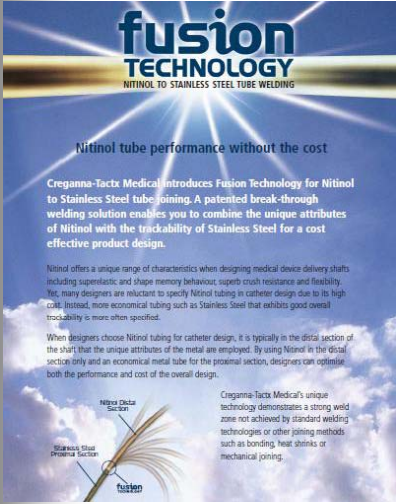
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Réduction des coûts



fusion
TECHNOLOGY
NITINOL TO STAINLESS STEEL TUBE WELDING

Nitinol tube performance without the cost

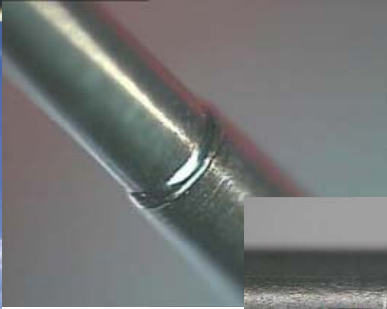
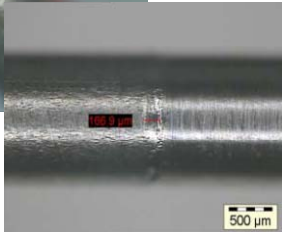
Creganna-Tactx Medical introduces Fusion Technology for Nitinol to Stainless Steel tube joining. A patented break-through welding solution enables you to combine the unique attributes of Nitinol with the trackability of Stainless Steel for a cost effective product design.

Nitinol offers a unique range of characteristics when designing medical device delivery shafts including superelastic and shape memory behaviour, superb crush resistance and flexibility. Yet, many designers are reluctant to specify Nitinol tubing in catheter design due to its high cost. Instead, more economical tubing such as Stainless Steel that exhibits good overall trackability is more often specified.

When designers choose Nitinol tubing for catheter design, it is typically in the distal section of the shaft that the unique attributes of the metal are employed. By using Nitinol in the distal section only and an economical metal tube for the proximal section, designers can optimize both the performance and cost of the overall design.

Creganna-Tactx Medical's unique technology demonstrates a strong weld zone not achieved by standard welding technologies or other joining methods such as bonding, heat shrink or mechanical joining.

Nitinol Distal Section
Stainless Steel Proximal Section

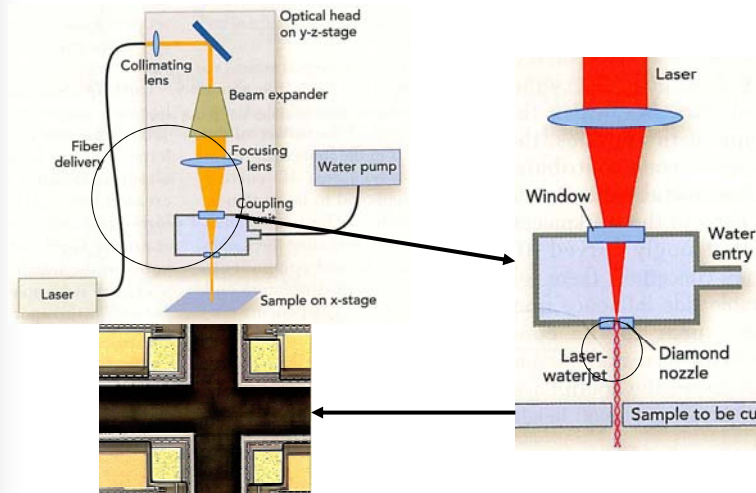
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Procédés Laser Hybride

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Procédés Hybrides/ Synova

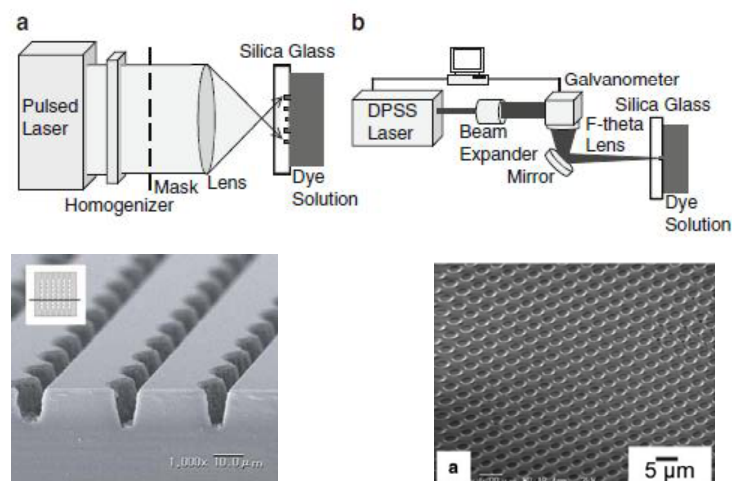


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Procédés Hybrides/ LIBWE

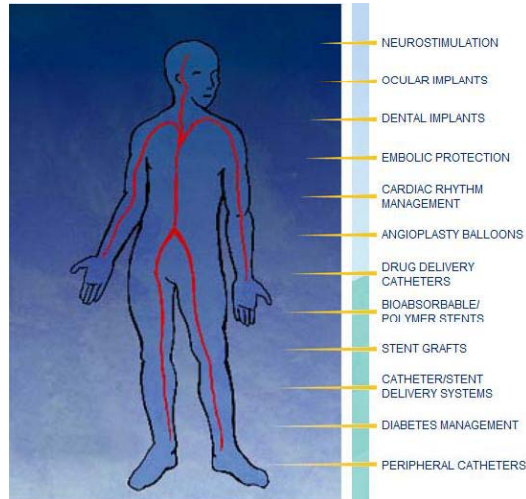


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Typical Laser Tasks for MDM:



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OPTEC ..the specialist in laser tools for medical device fabrication....
..non-contact, precise & clean laser machining of a wide range of technical polymers.....

Drilling.. (Pebax, PU)
...25µm dia

Insulation removal
..360° stripping of insulation from ultra-fine wires & bundles..

Generating structures..
..channels, nozzles, collectors.. lab on a chip (PC, PMMA, ..)

precision grooves, microvalves, channels, nozzles, collectors.. lab on a chip..

..opening contacts to spirally laid cables (PEEK)
opening to embedded contacts (PTFE & silicone)

..cleaning of contact pads.. patterning of polymer coated stents...

..want to talk to some experts in laser machining of medical devices?Try us.

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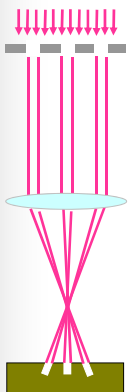
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Processing using Complex Motifs:-

...parallel patterning, generally suitable for big lasers

Illumination of a complex mask



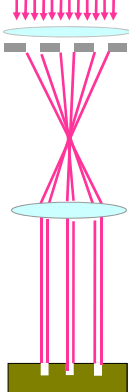
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- The complete pattern is projected in a single operation using a complex mask
- Inflexible but inherently suitable for mass production
- Stencil-type masks are limited to simply-connected motifs
- Metal/FS masks – any feature possible, & more precise, but costlier and lower damage threshold

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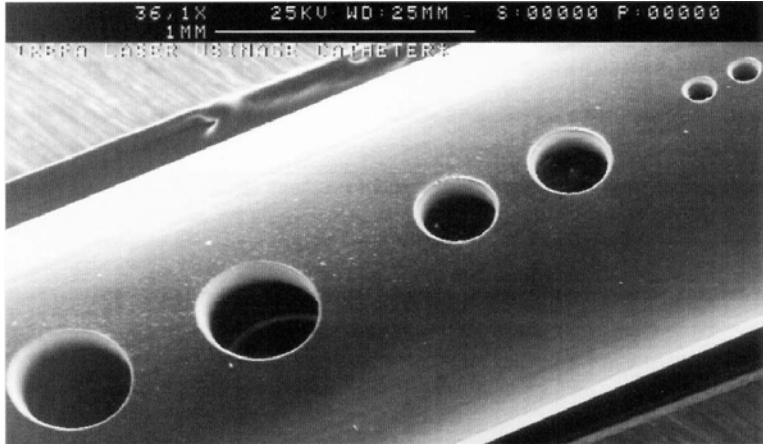
Telecentric imaging using a field lens



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Catheters machining

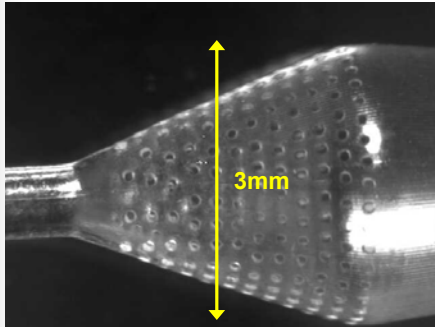


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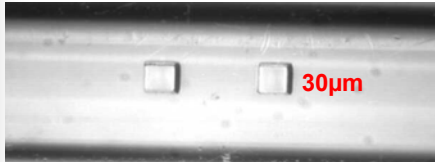
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3mm

Filter device(medical)



30µm

Catheter wall

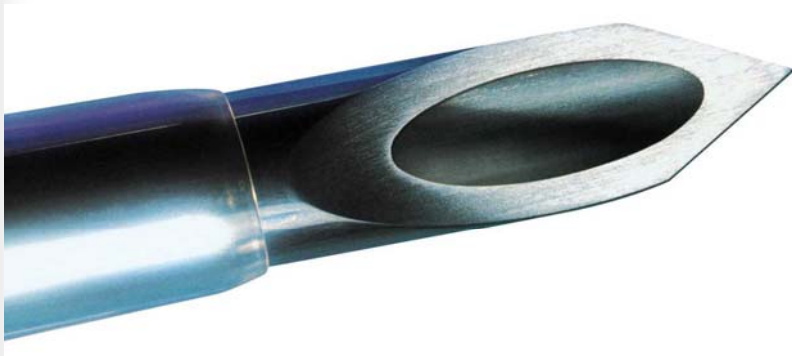
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Laser catheter chamfering

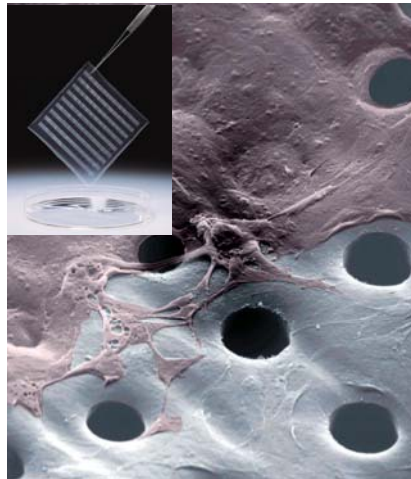


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Laser drilling of artificial skins

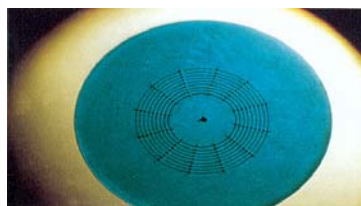


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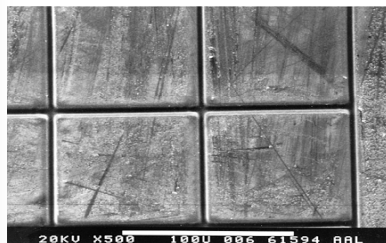
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Laser machining of medical components



- Machining of glass substrates



- Machining of counting grids

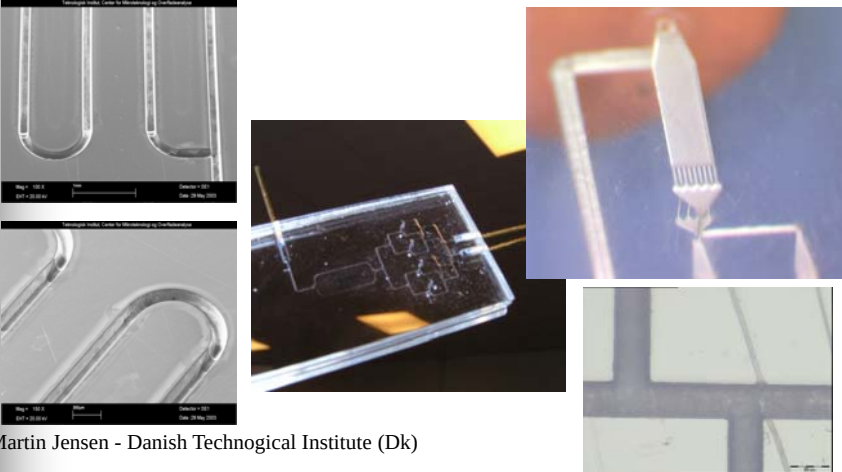
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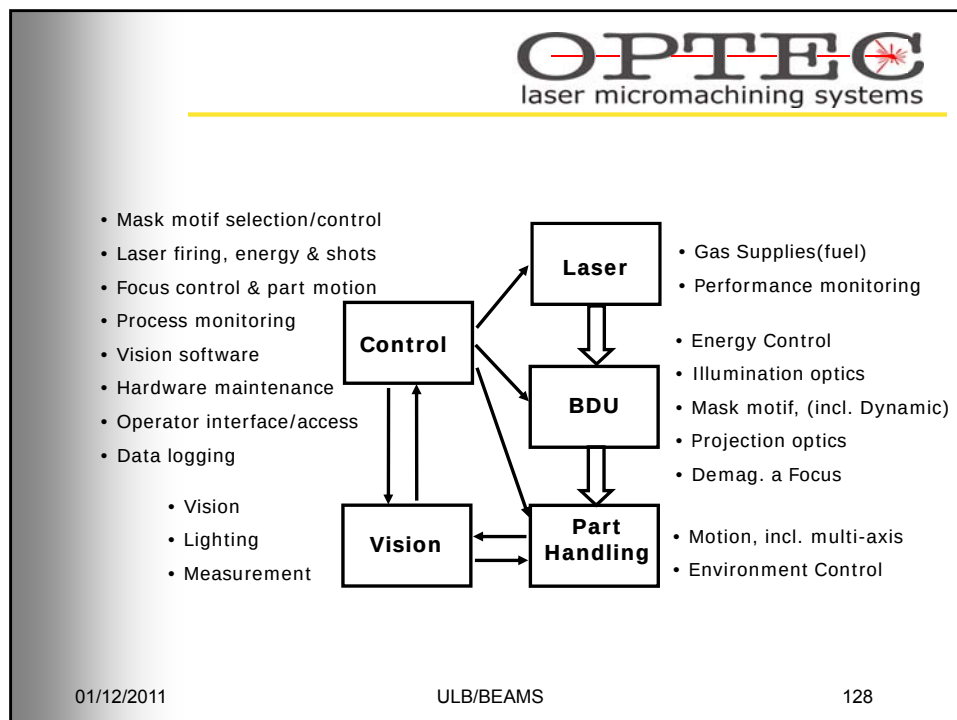
Laser machining of microfluidics: lab on a chip



Nigel Kent – NCSR (Irl)

Martin Jensen - Danish Technological Institute (Dk)

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FGSW,GSIG, IREPA LASER, Lasag,
Lightmotif, LPKF, LZH, Optec, Oxford Laser,
Rofin, Synova, TI

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Merci pour votre attention

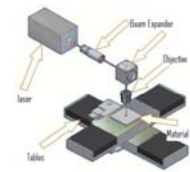
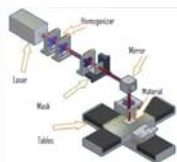
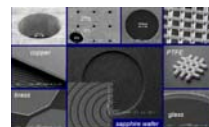
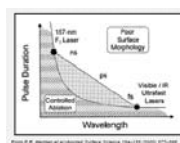
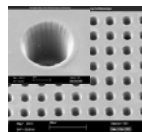
QUESTIONS....

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**Notre expertise dans le domaine du traitement
Athermique par laser :**



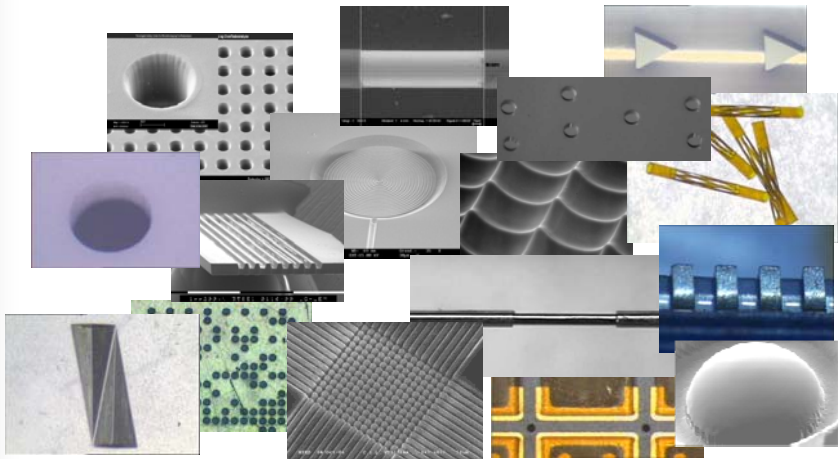
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Typical Micromachining Tasks:-



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